

Microcontrollers



Never stop thinking.

Edition 2000-05

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C504

8-Bit Single-Chip Microcontroller

Microcontrollers



C504

Revision History: 2000-05

Previous Version: 1996-05

Page	Subjects (major changes since last revision)					
35 - 40	OTP Memory Operation is added.					
41	Table on Version Byte Content is added.					
57 - 60	AC Characteristics of Programming Mode is added.					
several	$V_{ m CC}$ is replaced by $V_{ m DD}$.					
several	Specification for SAH-C504 is removed					

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8-Bit Single-Chip Microcontroller C500 Family

C504

C504

- Fully compatible to standard 8051 microcontroller
- Up to 40 MHz external operating frequency
- 16 Kbyte on-chip program memory
 - C504-2R: ROM version (with optional ROM protection)
 - C504-2E: programmable OTP version
 - C504-L: without on-chip program memory
- 256 byte on-chip RAM
- 256 byte on-chip XRAM
- Four 8-bit ports
 - 2 ports with mixed analog/digital I/O capability
- Three 16-bit timers/counters
 - Timer 2 with up/down counter feature

Further features are listed next page.

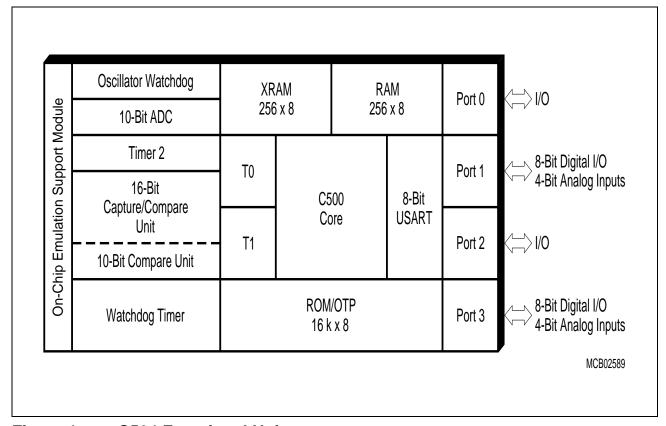


Figure 1 C504 Functional Units



- Capture/compare unit for PWM signal generation and signal capturing
 - 3-channel, 16-bit capture/compare unit
 - 1-channel, 10-bit compare unit
- Full duplex serial interface (USART)
- 10-bit A/D Converter with 8 multiplexed inputs
- Twelve interrupt sources with two priority levels
- On-chip emulation support logic (Enhanced Hooks Technology™)
- Programmable 15-bit Watchdog Timer
- Oscillator Watchdog
- Fast Power On Reset
- Power Saving Modes
 - Idle mode
 - Power-down mode with wake-up capability through INTO
- M-QFP-44 package
- Temperature ranges: SAB-C504 T_A : 0 to 70 °C

SAF-C504 T_A : - 40 to 85 °C SAK-C504 T_Δ : - 40 to 125 °C

(max. operating frequency: 24 MHz)

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code indentifies:

- The derivative itself, i.e. its function set
- the specified temperature range
- the package and the type of delivery

For the available ordering codes for the C504, please refer to the "**Product Information Microcontrollers**" which summarizes all available microcontroller variants.

Note: The ordering codes for the Mask-ROM versions are defined for each product after verification of the respective ROM code.



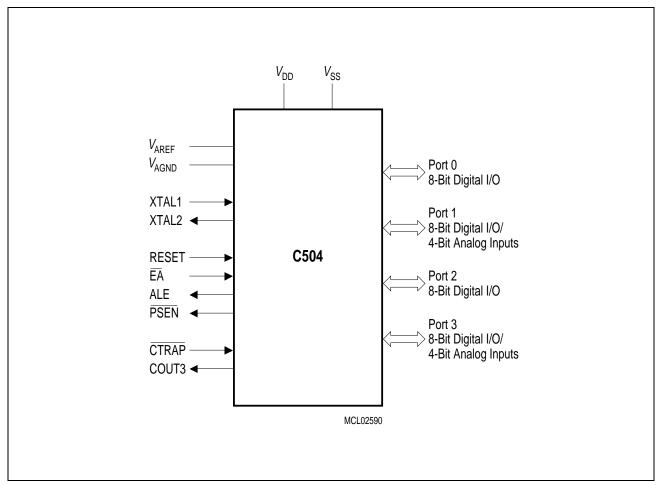


Figure 2 Logic Symbol



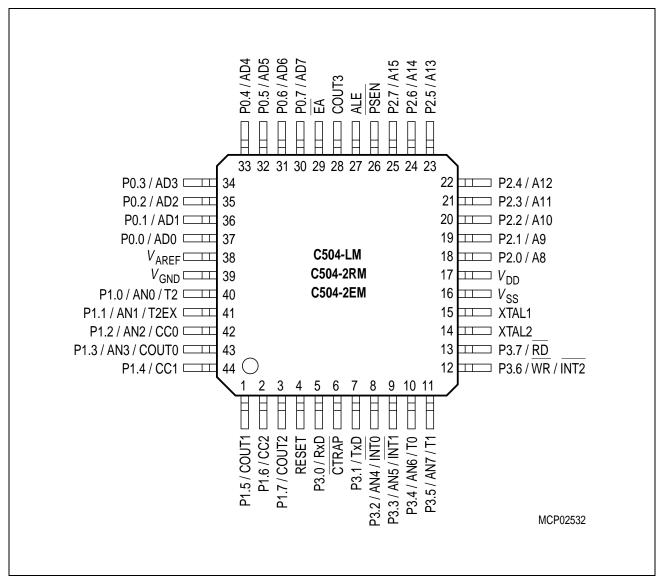


Figure 3 Pin Configuration (top view)



Table 1 Pin Definitions and Functions

Symbol	Pin Number (P-MQFP-44)	I/O ¹⁾	Function					
P1.0 - P1.7	40 - 44, 1 - 3	I/O	for digital input/output as analog inputs of the digital functions, Por and the Capture/Cor	al port. Port 1 pins can be used at. P1.0 - P1.3 can also be used the A/D converter. As secondary at 1 contains the Timer 2 pins appare inputs/outputs. Port 1 be used as analog inputs via				
			The functions are as follows:	signed to the pins of Port 1 as				
	40		P1.0 / AN0 / T2	Analog input channel 0 / input to Timer 2				
	41		P1.1 / AN1 / T2EX	Analog input channel 1 / capture/reload trigger of Timer 2 up-down count				
	42		P1.2 / AN2 / CC0	Analog input channel 2 / input/output of capture/ compare channel 0				
	43		P1.3 / AN3 / COUT0	Analog input channel 3 / output of capture/compare channel 0				
	44		P1.4 / CC1	Input/output of capture/ compare channel 1				
	1		P1.5 / COUT1	Output of capture/compare channel 1				
	2		P1.6 / CC2	Input/output of capture/ compare channel 2				
	3		P1.7 / COUT2	Output of capture/compare channel 2				
RESET	4	I	RESET A high level on this pin for two machine cycles where the oscillator is running resets the device. An internal diffused resistor to $V_{\rm SS}$ permits power-or reset using only an external capacitor to $V_{\rm DD}$.					



Table 1 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (P-MQFP-44)	I/O ¹⁾	Function	
P3.0 - P3.7	5, 7 - 13	I/O	Port 3	
			(T×D) operate as contain the externant four of the ana Port 3 pins are ass	onal port. P3.0 (R×D) and P3.1 defined for the C501. P3.2 to P3.7 al interrupt inputs, timer inputs, alog inputs of the A/D converter. igned to be used as analog inputs 2 P3ANA. P3.6/WR can be d interrupt input.
			The functions are follows:	assigned to the pins of port 3 as
	5		P3.0 / RxD	Receiver data input (asynch.) or data input/output (synch.) of serial interface
	7		P3.1 / TxD	Transmitter data output (asynch.) or clock output (synch.) of serial interface
	8		P3.2 / AN4 / INTO	Analog input channel 4 / external interrupt 0 input / Timer 0 gate control input
	9		P3.3 / AN5 / INT1	Analog input channel 5 / external interrupt 1 input / Timer 1 gate control input
	10		P3.4 / AN6 / T0	Analog input channel 6 / Timer 0 counter input
	11		P3.5 / AN7 / T1	Analog input channel 7 / Timer 1 counter input
	12		P3.6 / WR / INT2	WR control output; latches the data byte from port 0 into the external data memory / external interrupt 2 input
	13		P3.7 / RD	RD control output; enables the external data memory



Table 1 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (P-MQFP-44)	I/O ¹⁾	Function
CTRAP	6	I	CCU <u>Trap Input</u> With CTRAP = low, the compare outputs of the CAPCOM unit are switched to the logic level as defined in the COINI register (if they are enabled by the bits in SFR TRCON). CTRAP is an input pin with an internal pullup resistor. For power saving reasons, the signal source which drives the CTRAP input should be at high or floating level during power-down mode.
XTAL2	14	_	XTAL2 Output of the inverting oscillator amplifier.
XTAL1	15	_	Input to the inverting oscillator amplifier and input to the internal clock generator circuits. To drive the device from an external clock source, XTAL1 should be driven, while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is divided down by a divide-by-two flip-flop. Minimum and maximum high and low times as well as rise/fall times specified in the AC characteristics must be observed.
P2.0 - P2.7	18-25	I/O	is a bidirectional I/O port with internal pullup resistors. Port 2 pins that have "1"s written to them are pulled high by the internal pullup resistors, and in that state can be used as inputs. As inputs, Port 2 pins being externally pulled low will source current (I_{IL} , in the DC characteristics) because of the internal pullup resistors. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullup resistors when issuing "1"s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), Port 2 issues the contents of the P2 special function register.



Table 1 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (P-MQFP-44)	I/O ¹⁾	Function
PSEN	26	0	The Program Store Enable output is a control signal that enables the external program memory to the bus during external fetch operations. It is activated every six oscillator periods except during external data memory accesses. Remains high during internal program execution.
ALE	27	О	The Address Latch Enable output is used for latching the low-byte of the address into external memory during normal operation. It is activated every six oscillator periods except during an external data memory access. When instructions are executed from internal ROM (EA = 1) the ALE generation can be disabled by clearing bit EALE in SFR SYSCON.
COUT3	28	0	10-Bit compare channel output This pin is used for the output signal of the 10-bit Compare Timer 2 unit. COUT3 can be disabled and set to a high or low state.
ĒΑ	29	1	External Access Enable When held at high level, instructions are fetched from the internal ROM (C504-2R only) when the PC is less than 4000 _H . When held at low level, the C504 fetches all instructions from external program memory. For the C504-L, this pin must be tied low.
P0.0 - P0.7	37 - 30	I/O	Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have "1"s written to them float; and in that state, can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program or data memory. In this application, it uses strong internal pullup resistors when issuing "1" s. Port 0 also outputs the code bytes during program verification in the C504-2R. External pullup resistors are required during program (ROM) verification.
V_{AREF}	38	_	Reference voltage for the A/D converter.



Table 1 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (P-MQFP-44)	I/O ¹⁾	Function
$\overline{V_{AGND}}$	39	_	Reference ground for the A/D converter.
$\overline{V_{ t SS}}$	16	_	Ground (0 V)
$\overline{V_{DD}}$	17	_	Power Supply (+ 5 V)

¹⁾ I = Input,

O = Output



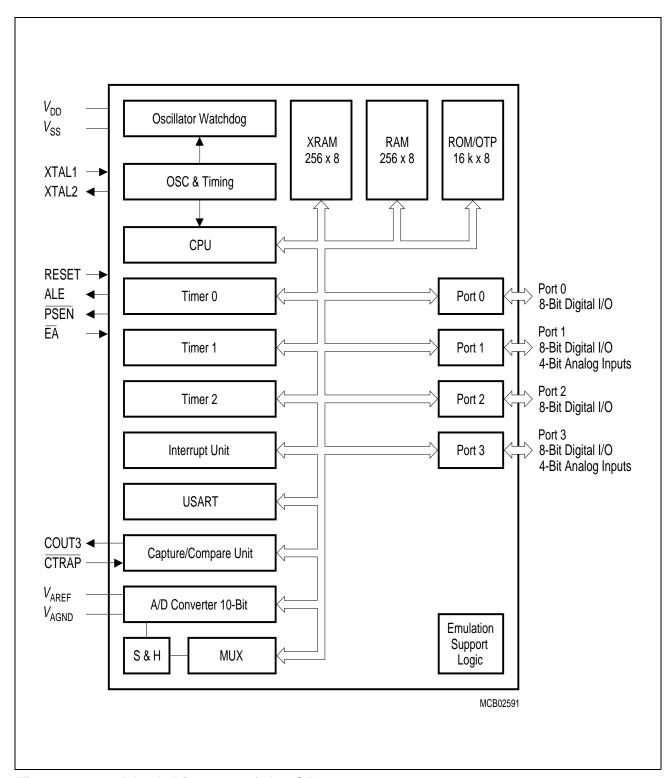


Figure 4 Block Diagram of the C504

Reset Value: 00_H



CPU

The C504 is efficient both as a controller and as an arithmetic processor. It has extensive facilities for binary and BCD arithmetic and excels in its bit-handling capabilities. Efficient use of program memory results from an instruction set consisting of 44% one-byte, 41% two-byte, and 15% three-byte instructions. With a 12 MHz crystal, 58% of the instructions are executed in 1.0 μ s (24 MHz: 500 ns, 40 MHz: 300 ns).

Special Function Register PSW (Address D0_H)

Bit No.	MSB	MSB							
					D3 _H				
D0 _H	CY	AC	F0	RS1	RS0	OV	F1	Р	PSW

Bit	Functio	n	
CY	Carry FI Used by	•	c instructions.
AC		y Carry F instructio	lag ns which execute BCD operations.
F0	General	Purpose	Flag 0
RS1 RS0	_		elect Control bits ed to select one of the four register banks.
	RS1	RS0	Function
	0	0	Bank 0 selected, data address 00 _H -07 _H
	0	1	Bank 1 selected, data address 08 _H -0F _H
	1	0	Bank 2 selected, data address 10 _H -17 _H
	1	1	Bank 3 selected, data address 18 _H -1F _H
OV	Overflow Used by	_	c instruction.
F1	General	Purpose	Flag 1
P		red by ha	rdware after each instruction to indicate an odd/one" bits in the accumulator.



Memory Organization

The C504 CPU manipulates operands in the following four address spaces:

- up to 64 Kbyte of program memory: 16K ROM for C504-2R 16K OTP for C504-2E
- up to 64 Kbyte of external data memory
- 256 bytes of internal data memory
- 256 bytes of internal XRAM data memory
- a 128 byte special function register area

Figure 5 illustrates the memory address spaces of the C504.

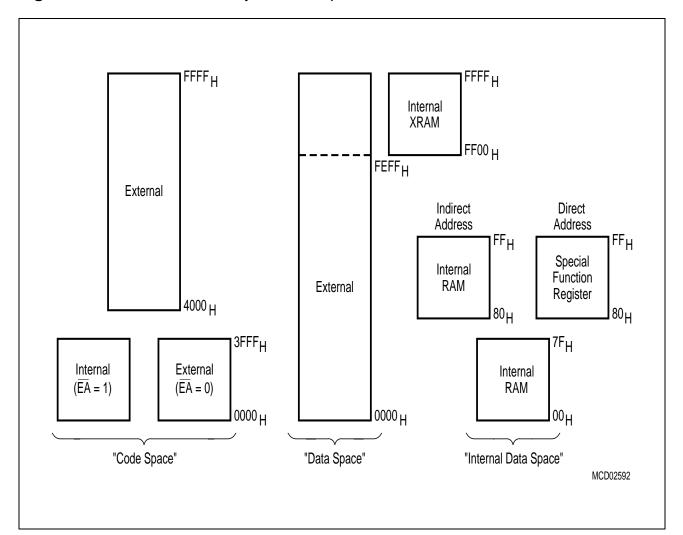


Figure 5 C504 Memory Map



Reset and System Clock Operation

The reset input is an active high input. An internal Schmitt trigger is used at the input for noise rejection. Since the reset is synchronized internally, the RESET pin must be held high for at least two machine cycles (24 oscillator periods) while the oscillator is running.

During reset, pins ALE and PSEN are configured as inputs and should not be stimulated externally. (An external stimulation at these lines during reset activates several test modes which are reserved for test purposes. This, in turn, may cause unpredictable output operations at several port pins).

At the reset pin, a pulldown resistor is internally connected to $V_{\rm SS}$ to allow a power-up reset with an external capacitor only. An automatic reset can be obtained when $V_{\rm DD}$ is applied by connecting the reset pin to $V_{\rm DD}$ via a capacitor. After $V_{\rm DD}$ has been turned on, the capacitor must hold the voltage level at the reset pin for a specific time to effect a complete reset.

The time required for a reset operation is the oscillator start-up time and the time for 2 machine cycles, which must be at least 10 - 20 ms, under normal conditions. This requirement is typically met using a capacitor of 4.7 to 10 μ F. The same considerations apply if the reset signal is generated externally (**Figure 6b**). In each case, it must be assured that the oscillator has started up properly and that at least two machine cycles have passed before the reset signal goes inactive.

Figure 6 shows the possible reset circuitries.

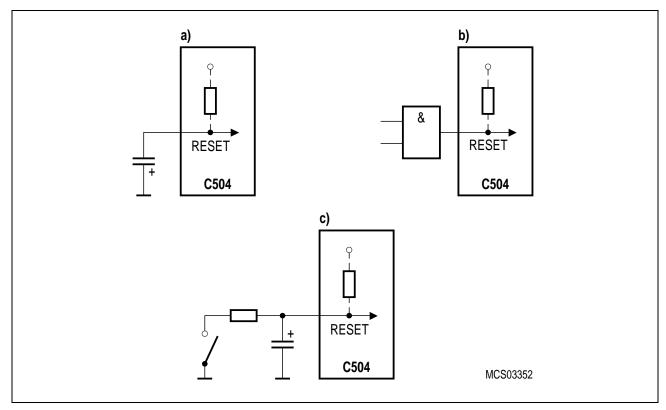


Figure 6 Reset Circuitries



Figure 7 shows the recommended oscillator circuit for the C504, while **Figure 8** shows the circuit for using an external clock source.

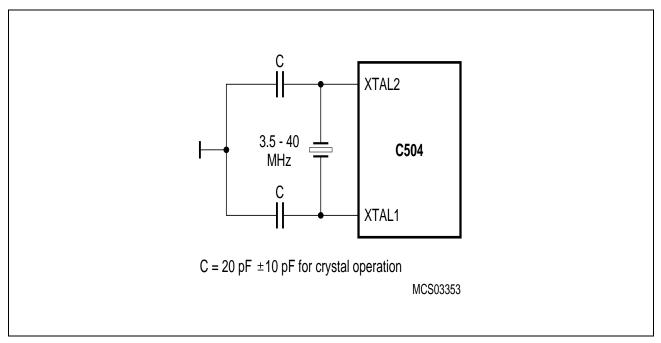


Figure 7 Recommended Oscillator Circuit

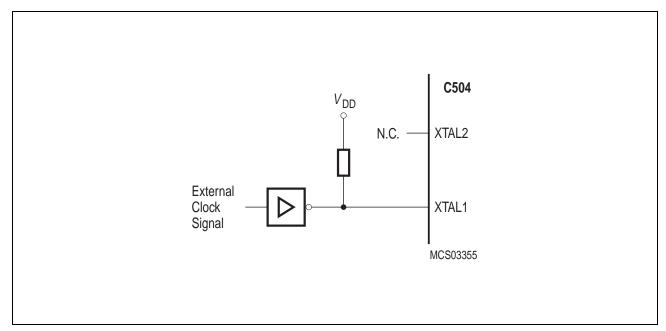


Figure 8 External Clock Source



Enhanced Hooks Emulation Concept

The Enhanced Hooks Emulation Concept of the C500 microcontroller family is a new, innovative way to control the execution of C500 MCUs and to gain extensive information on the internal operation of the controllers. Emulation of on-chip ROM based programs is possible, too.

Each production chip has built-in logic for the support of the Enhanced Hooks Emulation Concept. Therefore, no costly bond-out chips are necessary for emulation. This also ensure that emulation and production chips are identical.

The Enhanced Hooks TechnologyTM, which requires embedded logic in the C500 allows the C500 together with an EH-IC to function similar to a bond-out chip. This simplifies the design and reduces costs of an ICE-system. ICE-systems using an EH-IC and a compatible C500 are able to emulate all operating modes of the different versions of the C500. This includes emulation of ROM, ROM with code rollover and ROMless modes of operation. It is also able to operate in single step mode and to read the SFRs after a break.

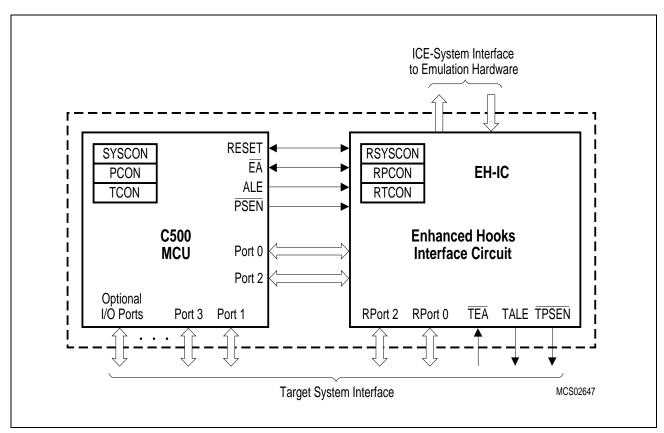


Figure 9 Basic C500 MCU Enhanced Hooks Concept Configuration

Port 0, Port 2 and some of the control lines of the C500 based MCU are used by Enhanced Hooks Emulation Concept to control the operation of the device during emulation and to transfer informations about the program execution and data transfer between the external emulation hardware (ICE-system) and the C500 MCU.



Special Function Registers

All registers, except the program counter and the four general purpose register banks, reside in the special function register area.

The 63 special function registers (SFR) include pointers and registers that provide an interface between the CPU and the other on-chip peripherals. All SFRs with addresses where address bits 0-2 are 0 (e.g. 80_H , 88_H , 90_H , 98_H , ..., $F0_H$, $F8_H$) are bit-addressable.

The SFRs of the C504 are listed in **Table 2** and **Table 3**. In **Table 2**, they are organized in groups which refer to the functional blocks of the C504. **Table 3** illustrates the contents of the SFRs in numeric order of their addresses.



Table 2 Special Function Registers - Functional Blocks

Block	Symbol	Name	Addr.	Contents after Reset
CPU	ACC B DPH DPL PSW SP SYSCON	Accumulator B-Register Data Pointer, High Byte Data Pointer, Low Byte Program Status Word Register Stack Pointer System Control Register	E0 _H ¹⁾ F0 _H ¹⁾ 83 _H 82 _H D0 _H ¹⁾ 81 _H B1 _H	00 _H 00 _H 00 _H 00 _H 00 _H 07 _H XX10XXX0 _B ³⁾
Interrupt System	IEN0 IEN1 CCIE ²⁾ IP0 IP1 ITCON	Interrupt Enable Register 0 Interrupt Enable Register 1 Capture/Compare Interrupt Enable Reg. Interrupt Priority Register 0 Interrupt Priority Register 1 Interrupt Trigger Condition Register	A8 _H ¹⁾ A9 _H D6 _H B8 _H ¹⁾ B9 _H 9A _H	0X000000 _B ³⁾ XX000000 _B ³⁾ 00 _H XX000000 _B ³⁾ XX000000 _B ³⁾ 00101010 _B
Ports	P0 P1 P1ANA ²⁾ P2 P3 P3ANA ²⁾	Port 0 Port 1 Port 1 Analog Input Selection Register Port 2 Port 3 Port 3 Analog Input Selection Register	80 _H ¹⁾ 90 _H ¹⁾ 90 _H ^{1) 4)} A0 _H ¹⁾ B0 _H ¹⁾	FF _H XXXX1111 _B ³⁾ FF _H FF _H XX1111XX _B ³⁾
A/D- Converter	ADCON0 ADCON1 ADDATH ADDATL P1ANA ²⁾ P3ANA ²⁾	A/D Converter Control Register 0 A/D Converter Control Register 1 A/D Converter Data Register High Byte A/D Converter Data Register Low Byte Port 1 Analog Input Selection Register Port 3 Analog Input Selection Register	D8 _H ¹⁾ DC _H D9 _H DA _H 90 _H ^{1) 4)} B0 _H ^{1) 4)}	XX000000 _B ³⁾ 01XXX000 _B ³⁾ 00 _H 00XXXXXX _B ³⁾ XXXX1111 _B ³⁾ XX1111XX _B ³⁾
Serial Channels	PCON ²⁾ SBUF SCON	Power Control Register Serial Channel Buffer Register Serial Channel Control Register	87 _H 99 _H 98_H ¹⁾	000X0000 _B XX _H ³⁾ 00 _H
Timer 0/ Timer 1	TCON TH0 TH1 TL0 TL1 TMOD	Timer 0/1 Control Register Timer 0, High Byte Timer 1, High Byte Timer 0, Low Byte Timer 1, Low Byte Timer Mode Register	88 _H ¹⁾ 8C _H 8D _H 8A _H 8B _H 89 _H	00 _H 00 _H 00 _H 00 _H 00 _H

¹⁾ Bit-addressable special function registers

²⁾ This special function register is listed repeatedly since some bits of it also belong to other functional blocks.

³⁾ X means that the value is undefined and the location is reserved

⁴⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.



Table 2 Special Function Registers - Functional Blocks (cont'd)

Block	Symbol	Name	Addr.	Contents after Reset
Timer 2	T2CON T2MOD RC2H RC2L TH2 TL2	Timer 2 Control Register Timer 2 Mode Register Timer 2 Reload Capture Register, High Byte Timer 2 Reload Capture Register, Low Byte Timer 2 High Byte Timer 2 Low Byte	C8 _H ¹⁾ C9 _H CB _H CA _H CC _H	00 _H XXXXXXX0 _B ³⁾ 00 _H 00 _H 00 _H
Capture / Compare Unit	CT1CON CCPL CCPH CT1OFL CT1OFH CMSEL0 CMSEL1 COINI TRCON CCL0 CCH0 CCH1 CCH1 CCL2 CCH2 CCH2 CCIR CCIE ²⁾ CT2CON CP2L CP2H CMP2H CMP2H BCON	Compare timer 1 control register Compare timer 1 period register, low byte Compare timer 1 offset register, low byte Compare timer 1 offset register, low byte Compare timer 1 offset register, high byte Capture/compare mode select register 0 Capture/compare mode select register 1 Compare output initialization register Trap enable control register Capture/compare register 0, low byte Capture/compare register 1, low byte Capture/compare register 1, low byte Capture/compare register 2, low byte Capture/compare register 2, high byte Capture/compare interrupt request flag reg. Capture/compare interrupt enable register Compare timer 2 control register Compare timer 2 period register, low byte Compare timer 2 period register, high byte Compare timer 2 compare register, high byte	$\begin{array}{c} {\rm E1_{H}} \\ {\rm DE_{H}} \\ {\rm DF_{H}} \\ {\rm E6_{H}} \\ {\rm E3_{H}} \\ {\rm E2_{H}} \\ {\rm C5_{H}} \\ {\rm C3_{H}} \\ {\rm C5_{H}} \\ {\rm C6_{H}} \\ {\rm C6_{H}} \\ {\rm C6_{H}} \\ {\rm D6_{H}} \\ {\rm D1_{H}} \\ {\rm D3_{H}} \\ {\rm D5_{H}} \\ {\rm D7_{H}} \end{array}$	00010000 _B 00 _H
Watchdog Timer	WDCON WDTREL	Watchdog Timer Control Register Watchdog Timer Reload Register	C0_H ¹⁾ 86 _H	XXXX0000 _B ³⁾
Power Saving Mode	PCON ²⁾ PCON1	Power Control Register Power Control Register 1	87 _H 88 _H ^{1) 4)}	000X0000 _B ³⁾ 0XXXXXXX _B ³⁾

¹⁾ Bit-addressable special function registers

²⁾ This special function register is listed repeatedly since some bits of it also belong to other functional blocks.

³⁾ X means that the value is undefined and the location is reserved

⁴⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.



Table 3 Contents of the SFRs, SFRs in Numeric Order of their Addresses

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
80 _H ²⁾	P0	FF _H	.7	.6	.5	.4	.3	.2	.1	.0
81 _H	SP	07 _H	.7	.6	.5	.4	.3	.2	.1	.0
82 _H	DPL	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
83 _H	DPH	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
86 _H	WDTREL	00 _H	WDT PSEL	.6	.5	.4	.3	.2	.1	.0
87 _H	PCON	000X- 0000 _B	SMOD	PDS	IDLS	_	GF1	GF0	PDE	IDLE
88 _H ²⁾	TCON	00 _H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
88 _H ¹⁾³⁾	PCON1	0XXX- XXXX _B	EWPD	-	_	-	-	_	-	_
89 _H	TMOD	00 _H	GATE	C/T	M1	МО	GATE	C/T	M1	МО
8A _H	TL0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8B _H	TL1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8C _H	TH0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
8D _H	TH1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
90 _H ²⁾	P1	FF _H	.7	.6	.5	.4	.3	.2	T2EX	T2
90 _H ²⁾³⁾	P1ANA	XXXX- 1111 _B	_	_	_	_	EAN3	EAN2	EAN1	EAN0
98 _H ²⁾	SCON	00 _H	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
99 _H	SBUF	XX _H	.7	.6	.5	.4	.3	.2	.1	.0
9A _H	ITCON	0010- 1010 _B	IT2	IE2	I2ETF	I2ETR	I1ETF	I1ETR	I0ETF	I0ETR
A0 _H ²⁾	P2	FF _H	.7	.6	.5	.4	.3	.2	.1	.0
A8 _H ²⁾	IEN0	0X00- 0000 _B	EA	-	ET2	ES	ET1	EX1	ET0	EX0
A9 _H	IEN1	XX00- 0000 _B	_	_	ECT1	ECCM	ECT2	ECEM	EX2	EADC

¹⁾ X means that the value is undefined and the location is reserved

²⁾ Bit-addressable special function registers

³⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.



Table 3 Contents of the SFRs, SFRs in Numeric Order of their Addresses (cont'd)

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
B0 _H ²⁾	P3	FF _H	RD	WR	T1	T0	INT1	INT0	TxD	RxD
B0 _H ²⁾³⁾	P3ANA	XX11- 11XX _B	-	-	EAN7	EAN6	EAN5	EAN4	-	-
B1 _H	SYSCON	XX10- XXX0 _B	-	-	EALE	RMAP	-	_	_	XMAP
B8 _H ²⁾	IP0	XX00- 0000 _B	-	-	PT2	PS	PT1	PX1	PT0	PX0
B9 _H	IP1	XX00- 0000 _B	-	-	PCT1	PCCM	PCT2	PCEM	PX2	PADC
C0 _H ²⁾	WDCON	XXXX- 0000 _B	-	-	-	-	OWDS	WDTS	WDT	SWDT
C1 _H	CT2CON	0001- 0000 _B	CT2P	ECT2O	STE2	CT2 RES	CT2R	CLK2	CLK1	CLK0
C2 _H	CCL0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C3 _H	CCH0	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C4 _H	CCL1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C5 _H	CCH1	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C6 _H	CCL2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C7 _H	CCH2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
C8 _H ²⁾	T2CON	00 _H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/ RL2
C9 _H	T2MOD	XXXX- XXX0 _B	-	-	_	_	-	_	_	DCEN
CA _H	RC2L	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CB _H	RC2H	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CCH	TL2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CD _H	TH2	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
CF _H	TRCON	00 _H	TRPEN	TRF	TREN5	TREN4	TREN3	TREN2	TREN1	TREN0

¹⁾ X means that the value is undefined and the location is reserved

²⁾ Bit-addressable special function registers

³⁾ SFR is located in the mapped SFR area. For accessing this SFR, bit RMAP in SFR SYSCON must be set.



Table 3 Contents of the SFRs, SFRs in Numeric Order of their Addresses (cont'd)

Addr	Register	Content after Reset ¹⁾	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
D0 _H ²⁾	PSW	00 _H	CY	AC	F0	RS1	RS0	OV	F1	Р
D2 _H	CP2L	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
D3 _H	CP2H	XXXX. XX00 _B	-	-	1	-	-	-	.1	.0
D4 _H	CMP2L	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
D5 _H	CMP2H	XXXX. XX00 _B	ı	ı	ı	ı	ı	ı	.1	.0
D6 _H	CCIE	00 _H	ECTP	ECTC	CC2 FEN	CC2 REN	CC1 FEN	CC1 REN	CC0 FEN	CC0 REN
D7 _H	BCON	00 _H	BCMP BCEM	PWM1	PWM0	EBCE	BCERR	BCEN	BCM1	всмо
D8 _H ²⁾	ADCON0	XX00- 0000 _B	1	1	IADC	BSY	ADM	MX2	MX1	MX0
D9 _H	ADDATH	00 _H	.9	.8	.7	.6	.5	.4	.3	.2
DA _H	ADDATL	00XX- XXXX _B	.1	0.	-	-	I	-	_	_
DC _H	ADCON1	01XX- X000 _B	ADCL1	ADCL0	ı	ı	ı	MX2	MX1	MX0
DE _H	CCPL	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
DF _H	ССРН	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
E0 _H ²⁾	ACC	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
E1 _H	CT1CON	0001- 0000 _B	СТМ	ETRP	STE1	CT1 RES	CT1R	CLK2	CLK1	CLK0
E2 _H	COINI	FF _H	COUT 3I	COUTX I	COUT 2I	CC2I	COUT 1I	CC1I	COUT 0I	CC0I
E3 _H	CMSEL0	00 _H	CMSEL 13	CMSEL 12	CMSEL 11	CMSEL 10	CMSEL 03	CMSEL 02	CMSEL 01	CMSEL 00
E4 _H	CMSEL1	00 _H	0	0	0	0	CMSEL 23	CMSEL 22	CMSEL 21	CMSEL 20
E5 _H	CCIR	00 _H	CT1FP	CT1FC	CC2F	CC2R	CC1F	CC1R	CC0F	CC0R
E6 _H	CT10FL	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
E7 _H	CT10FH	00 _H	.7	.6	.5	.4	.3	.2	.1	.0
F0 _H ²⁾	В	00 _H	.7	.6	.5	.4	.3	.2	.1	.0

¹⁾ X means that the value is undefined and the location is reserved

²⁾ Bit-addressable special function registers



Timer/Counter 0 and 1

Timer/Counter 0 and 1 can be used in four operating modes as listed in Table 4.

Table 4	Timer/Counter 0 and 1	Operating Modes
---------	-----------------------	------------------------

Mode	Description	TMOD				Input Clock		
		Gate	C/T	M1	МО	internal	external (max.)	
0	8-bit timer/counter with a divide-by-32 prescaler	Х	Х	0	0	$f_{\rm OSC}/12 \times 32$	$f_{\rm OSC}/24 \times 32$	
1	16-bit timer/counter	Х	Х	1	1	f _{OSC} /12	$f_{\rm OSC}/24$	
2	8-bit timer/counter with 8-bit auto-reload	Х	Х	0	0	f _{OSC} /12	$f_{\rm OSC}/24$	
3	Timer/counter 0 used as one 8-bit timer/counter and one 8-bit timer Timer 1 stops	Х	X	1	1	f _{OSC} /12	$f_{\rm OSC}/24$	

In the "timer" function (C/ \overline{T} = '0'), the register is incremented every machine cycle. Therefore the count rate is $f_{OSC}/12$.

In the "counter" function the register is incremented in response to a 1-to-0 transition at its corresponding external input pin (P3.4/T0, P3.5/T1). Since it takes two <u>machine cycles</u> to detect a falling edge the max. count rate is $f_{\rm OSC}/24$. External inputs INT0 and INT1 (P3.2, P3.3) can be programmed to function as a gate to facilitate pulse width measurements. **Figure 10** illustrates the input clock logic.

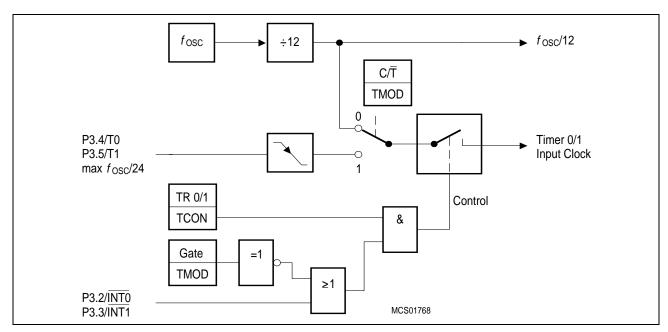


Figure 10 Timer/Counter 0 and 1 Input Clock Logic



Timer/Counter 2

Timer 2 is a 16-bit Timer/Counter with an up/down count feature. It can operate either as a timer or as an event counter. This is selected by bit $C/\overline{T2}$ of SFR T2CON. It has three operating modes as shown in **Table 5**.

Table 5 Timer/Counter 2 Operating Modes

Mode	T2	CON		T2MOD	T2CON	P1.1/	Remarks	Input Clock	
	R×CLK or T×CLK	CP/ RL2	TR2	DCEN	EXEN	T2EX		internal	external (P1.0/T2)
16-bit Auto- reload	0	0	1	0	0	X ↓	reload upon overflow reload trigger	f _{OSC} /12	$\max_{f_{\rm OSC}/24}$
	0	0	1	1 1	X X	0	(falling edge) Down counting Up counting		
16-bit Cap- ture	0	1	1	X	0	X ↓	16 bit Timer/ Counter (only up-counting) capture TH2, TL2 → RC2H, RC2L	f _{OSC} /12	max $f_{OSC}/24$
Baud Rate Gene- rator	1	X	1	X	0	x ↓	no overflow interrupt request (TF2) extra external interrupt ("Timer 2")	f _{OSC} /2	max $f_{\rm OSC}/24$
off	Х	Х	0	Х	Х	Х	Timer 2 stops	_	_

Note: $\downarrow = \neg$ falling edge



Capture/Compare Unit

The Capture/Compare Unit (CCU) of the C504 consists of a 16-bit 3-channel capture/compare unit (CAPCOM) and a 10-bit 1-channel compare unit (COMP). In compare mode, the CAPCOM unit provides two output signals per channel, which can have inverted signal polarity and non-overlapping pulse transitions. The COMP unit can generate a single PWM output signal and is further used to modulate the CAPCOM output signals. In capture mode, the value of the Compare Timer 1 is stored in the capture registers if a signal transition occurs at the pins CCx. **Figure 11** shows the block diagram of the CCU.

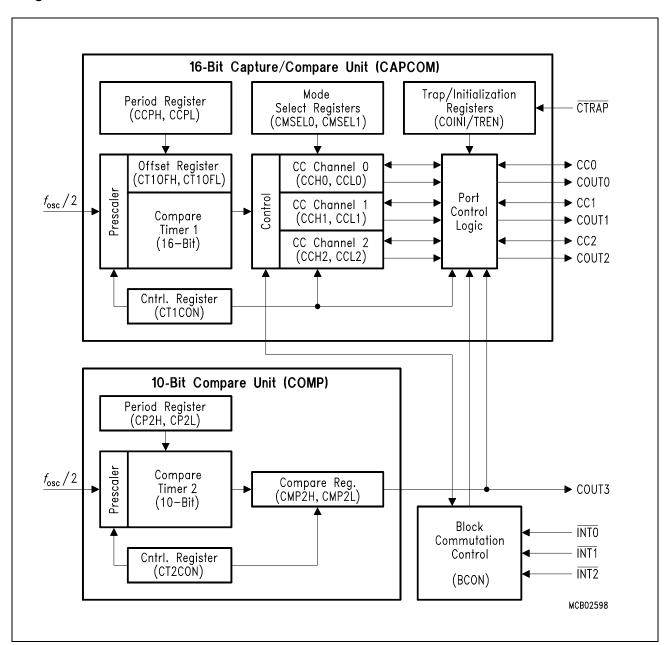


Figure 11 Block Diagram of the CCU



The Compare Timers 1 and 2 are free running, processor clock coupled 16-bit / 10-bit timers; each of which has a count rate with a maximum of $f_{\rm osc}/2$ up to $f_{\rm osc}/256$. The compare timer operations with its possible compare output signal waveforms are shown in **Figure 12**.

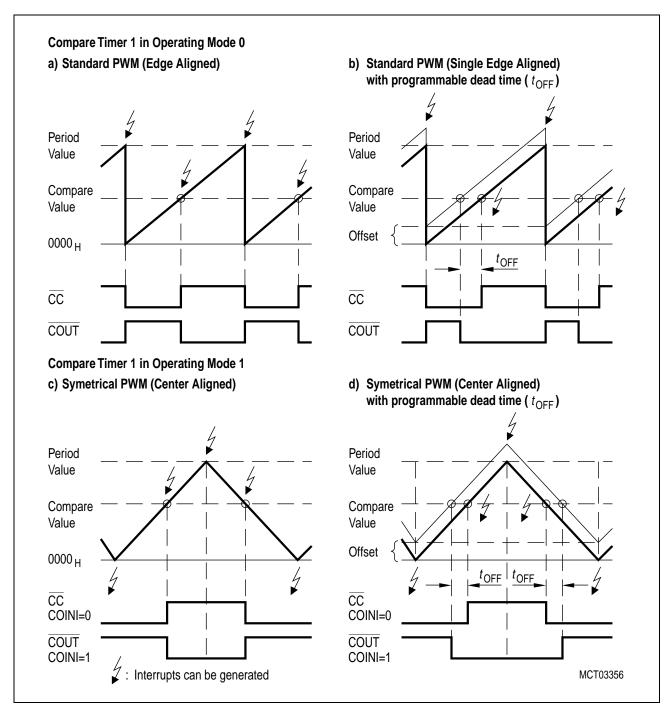


Figure 12 Basic Operating Modes of the CAPCOM Unit

Compare Timer 1 can be programmed for both operating modes while Compare Timer 2 works only in operating mode 0 with one output signal of selectable polarity at the pin COUT3.



Serial Interface (USART)

The serial port is full duplex and can operate in four modes (one synchronous mode, three asynchronous modes) as illustrated in **Table 6**. The possible baud rates can be calculated using the formulas given in **Table 6**.

Table 6 USART Operating Modes

Mode	SCON		Baud Rate	Description		
	SM0	SM1				
0	0	0	f _{OSC} /12	Serial data enters and exits through R×D. T×D outputs the shift clock. 8-bit are transmitted/received (LSB first)		
1	0	1	Timer 1/2 overflow rate	8-bit UART 10 bits are transmitted (through T×D) or received (R×D)		
2	1	0	$f_{ m OSC}/32$ or $f_{ m OSC}/64$	9-bit UART 11 bits are transmitted (T×D) or received (R×D)		
3	1	1	Timer 1/2 overflow rate	9-bit UART Like mode 2 except the variable baud rate		

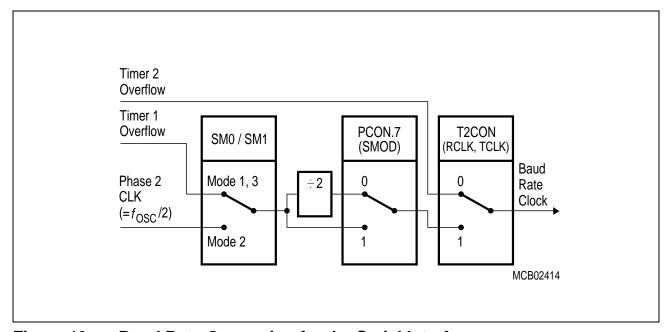


Figure 13 Baud Rate Generation for the Serial Interface



The possible baud rates can be calculated using the formulas given in **Table 7**.

 Table 7
 Formulas for Calculating Baud Rates

Source of Baud Rate	Operating Mode	Baud Rate
Oscillator	0 2	$f_{\text{OSC}}/12$ $(2^{\text{SMOD}} \times f_{\text{OSC}})/64$
Timer 1 (16-bit timer) (8-bit timer with 8-bit auto-reload)	1, 3 1, 3	$(2^{\rm SMOD} imes {\rm timer~1~overflow~rate})/32 \ (2^{\rm SMOD} imes f_{\rm OSC})/(32 imes 12 imes (256-{\rm TH1}))$
Timer 2	1, 3	$f_{\rm OSC}/(32 \times (65536-(RC2H, RC2L))$



10-Bit A/D Converter

The C504 has a high performance 8-channel 10-bit A/D converter using successive approximation technique for the conversion of analog input voltages. **Figure 14** shows the block diagram of the A/D Converter.

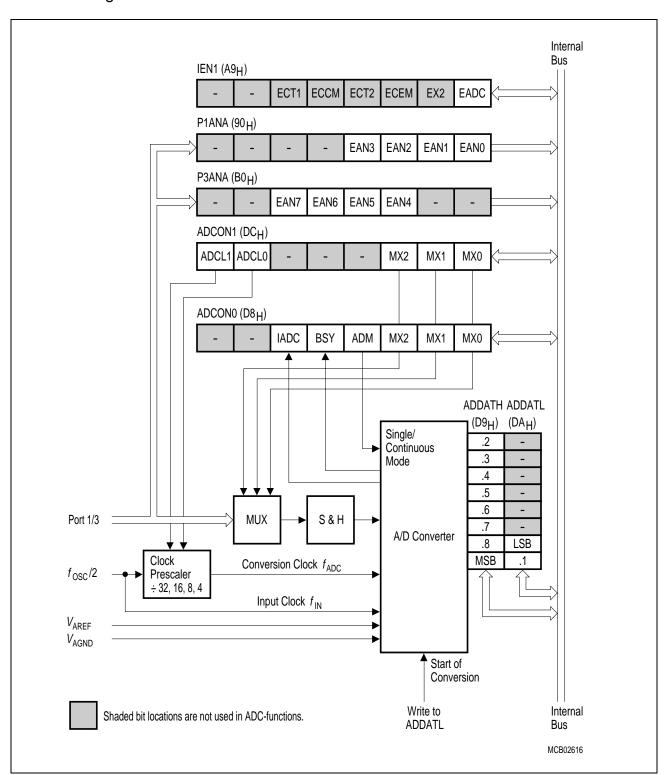


Figure 14 A/D Converter Block Diagram



The A/D Converter uses two clock signals for operation: the conversion clock $f_{\rm ADC}$ (= 1/ $t_{\rm ADC}$) and the input clock $f_{\rm IN}$ (= 1/ $t_{\rm IN}$). Both clock signals are derived from the C504 system clock $f_{\rm OSC}$ which is applied at the XTAL pins. The duration of an A/D conversion is a multiple of the period of the $f_{\rm IN}$ clock signal. The table in **Figure 15** shows the prescaler ratios and the resulting A/D conversion times which must be selected for typical system clock rates.

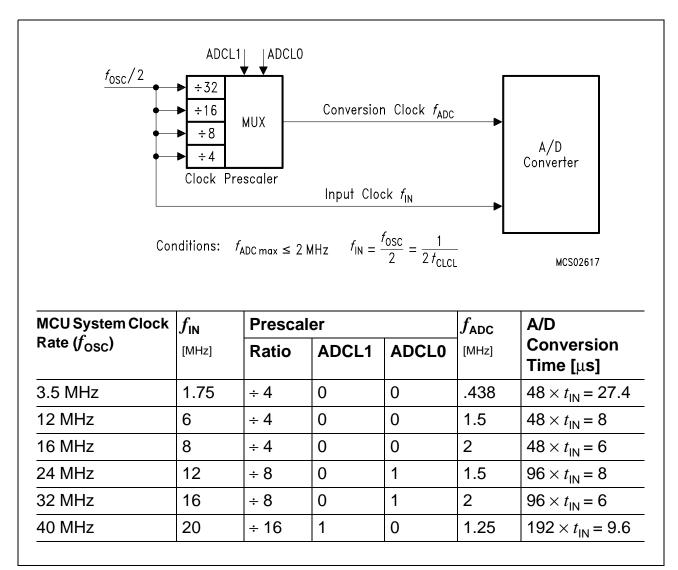


Figure 15 A/D Converter Clock Selection

The analog inputs are located at Port 1 and Port 3 (4 lines on each port). The corresponding Port 1 and Port 3 pins have a port structure, which allows the pins to be used either as digital I/Os or analog inputs. The analog input function of these mixed digital/analog port lines is selected via the registers P1ANA and P3ANA.



Interrupt System

The C504 provides 12 interrupt sources with two priority levels. **Figures 16** and **17** give a general overview of the interrupt sources and illustrate the interrupt request and control flags.

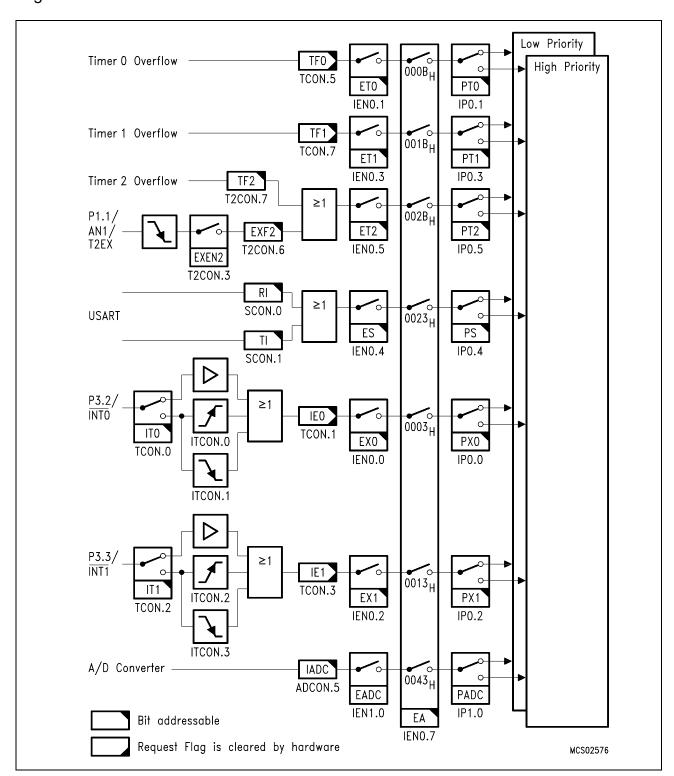


Figure 16 Interrupt Request Sources (Part 1)



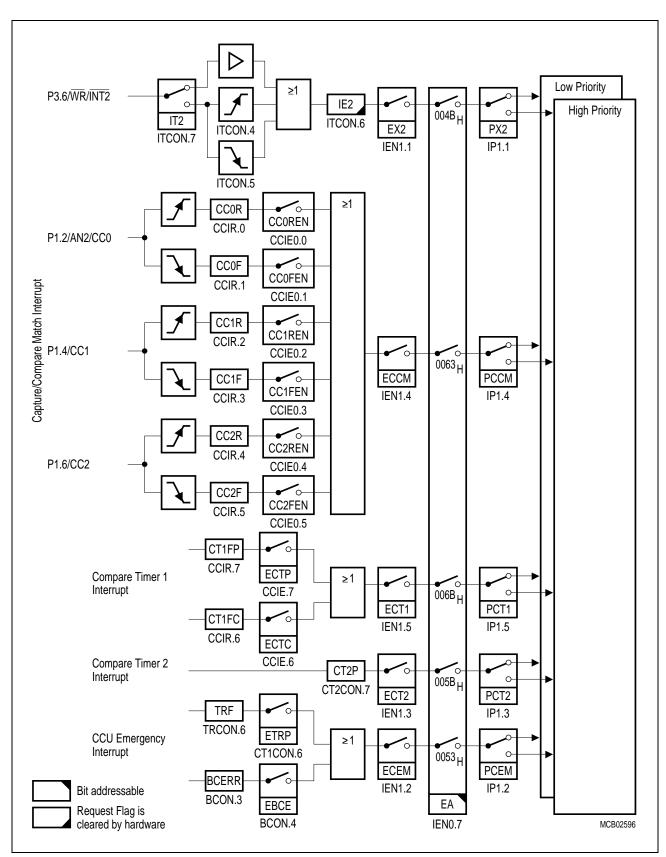


Figure 17 Interrupt Request Sources (Part 2)



Table 8 Interrupt Vector Addresses

Request Flags	Interrupt Source	Vector Address
IE0	External interrupt 0	0003 _H
TF0	Timer 0 interrupt	000B _H
IE1	External interrupt 1	0013 _H
TF1	Timer 1 interrupt	001B _H
RI + TI	Serial port interrupt	0023 _H
TF2 + EXF2	Timer 2 interrupt	002B _H
IADC	A/D converter interrupt	0043 _H
IE2	External interrupt 2	004B _H
TRF, BCERR	CAPCOM emergency interrupt	0053 _H
CT2P	Compare timer 2 interrupt	005B _H
CC0F-CC2F, CC0R-CC2R	Capture/compare match interrupt	0063 _H
CT1FP, CT1FC	Compare timer 1 interrupt	006B _H
	Power-down interrupt	007B _H

A low-priority interrupt can itself be interrupted by a high-priority interrupt, but not by another low-priority interrupt. A high-priority interrupt cannot be interrupted by any other interrupt sources.

If two requests of different priority level are received simultaneously, the request of higher priority is serviced. If requests of the same priority are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence as shown in **Table 9**.

 Table 9
 Interrupt Source Structure

Interrupt Source		Priority
High Priority	— Low Priority	
External Interrupt 0	A/D Converter	High
Timer 0 Interrupt	External Interrupt 2	
External Interrupt 1	CCU Emergency Interrupt	
Timer 1 Interrupt	Compare Timer 2 Interrupt	↓
Serial Channel	Capture/Compare Match Interrupt	
Timer 2 Interrupt	Compare Timer 1 Interrupt	Low



Fail Save Mechanisms

The C504 offers enhanced fail save mechanisms, which allow an automatic recovery from software or hardware failure.

- a programmable 15-bit Watchdog Timer
- Oscillator Watchdog

Programmable Watchdog Timer

The Watchdog Timer in the C504 is a 15-bit timer, which is incremented by a count rate of either $f_{\text{CYCLE}}/2$ or $f_{\text{CYCLE}}/32$ ($f_{\text{CYCLE}} = f_{\text{OSC}}/12$). Only the upper 7 bits of the 15-bit watchdog timer count value can be programmed. **Figure 18** shows the block diagram of the programmable Watchdog Timer.

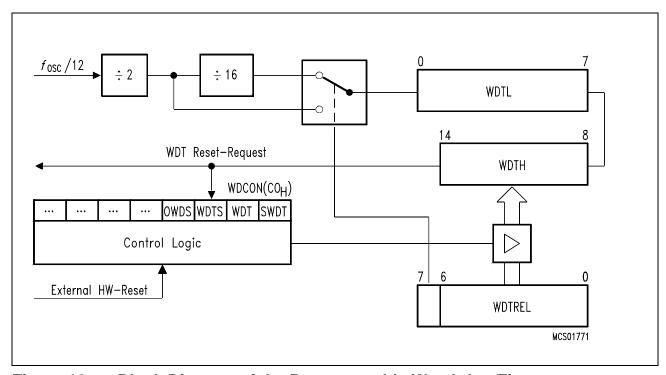


Figure 18 Block Diagram of the Programmable Watchdog Timer

The Watchdog Timer can be started by software (bit SWDT in SFR WDCON), but it cannot be stopped during active mode of the device. If the software fails to refresh the running Watchdog Timer, an internal reset will be initiated. The reset cause (external reset or reset caused by the watchdog) can be examined by software (status flag WDTS in SFR WDCON is set). A refresh of the Watchdog Timer is done by setting bits WDT and SWDT (both in SFR WDCON) consecutively.

This double instruction sequence has been implemented to increase system security. It must be noted, however, that the Watchdog Timer is halted during the idle mode and power down mode of the processor.



Oscillator Watchdog

The Oscillator Watchdog of the C504 serves for three functions:

Monitoring of the on-chip oscillator's function

The watchdog supervises the on-chip oscillator's frequency; if it is lower than the frequency of an auxiliary RC oscillator, the internal clock is supplied by this RC oscillator and the C504 is brought into reset. If the failure condition disappears, the C504 executes a final reset phase of typically 1 ms in order to allow the oscillator to stabilize; then, the Oscillator Watchdog reset is released and the part starts program execution again.

Fast internal reset after power-on

The oscillator watchdog unit provides a clock supply for the reset before the on-chip oscillator has started. The Oscillator Watchdog unit also works identically to the monitoring function.

Control of external wake-up from software power-down mode

When the software power-down mode is terminated by a low level at pin P3.2/INTO, the Oscillator Watchdog unit ensures that the microcontroller resumes operation (execution of the power-down wake-up interrupt) with the nominal clock rate. In the power-down mode, the RC oscillator and the on-chip oscillator are stopped. Both oscillators are started again when power-down mode is released. When the on-chip oscillator has a higher frequency than the RC oscillator, the microcontroller starts operation after a final delay of typically 1 ms in order to allow the on-chip oscillator to stabilize.



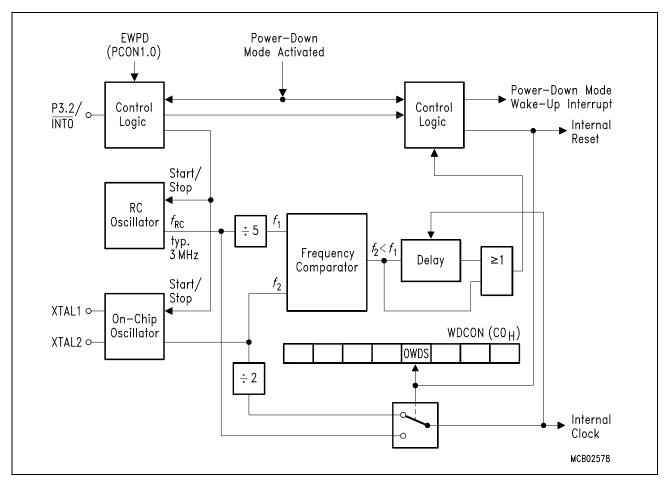


Figure 19 Block Diagram of the Oscillator Watchdog

Power Saving Modes

The C504 provides two power saving modes, the idle mode and the power down mode.

- In the <u>idle mode</u>, the oscillator of the C504 continues to run, but the CPU is gated off from the clock signal. However, the interrupt system, the serial port, the A/D Converter, and all timers with the exception of the Watchdog Timer, are further provided with the clock. The CPU status is preserved in its entirety: the stack pointer, program counter, program status word, accumulator, and all other registers maintain their data during idle mode.
- In the <u>power down</u> mode, the RC oscillator and the on-chip oscillator which operates with the XTAL pins are both stopped. Therefore all functions of the microcontroller are stopped and only the contents of the on-chip RAM, XRAM and the SFRs are maintained. The port pins, which are controlled by their port latches, output the values that are held by their SFRs.

Table 10 gives a general overview of the entry and exit procedures of the power saving modes.



Table 10 Power Saving Modes Overview

Mode	Entering (2-Instruction Example)	Leaving by	Remarks		
Idle mode	ORL PCON, #01H ORL PCON, #20H	Occurrence of any enabled interrupt	CPU clock is stopped; CPU maintains their data;		
		Hardware Reset	peripheral units are active (if enabled) and provided with clock.		
Power	With external wake-up	Hardware Reset	Oscillator is stopped;		
Down mode	capability from power down enabled	P3.2/INT0 goes low for at least	Contents of on-chip RAM and SFRs are maintained.		
	ORL SYSCON,#10H ORL PCON1,#80H ANL SYSCON,#0EFH	10 μs. It is desired that the pin be held at high level during the			
	ORL PCON,#02H ORL PCON,#40H	power down mode entry and up to the wake-up.			
	With external wake-up capability from power down disabled ORL PCON,#02H ORL PCON,#40H	Hardware Reset			

If a power saving mode is terminated through an interrupt, including the external wakeup via P3.2/INT0, the microcontroller state (CPU, ports, peripherals) remains preserved. If it is terminated by a hardware reset, the microcontroller is reset to its default state.

In the power down mode of operation, $V_{\rm DD}$ can be reduced to minimize power consumption. It must be ensured, however, that $V_{\rm DD}$ is not reduced before the power down mode is invoked, and that $V_{\rm DD}$ is restored to its normal operating level, before the power down mode is terminated.



OTP Memory Operation (C504-2E only)

The C504-2E is the OTP version of the C504 microcontroller with a 16Kbyte one-time programmable (OTP) program memory. Fast programming cycles are achieved (1 byte in 100 μ s) with the C504-2E. Several levels of OTP memory protection can be selected as well.

To program the device, the C504-2E must be put into the programming mode. Typically, this is not done in-system, but in a special programming hardware. In the programming mode, the C504-2E operates as a slave device similar to an EPROM standalone memory device and must be controlled with address/data information, control lines, and an external 11.5 V programming voltage.

Figure 20 shows the pins of the C504-2E which are required for controlling of the OTP programming mode.

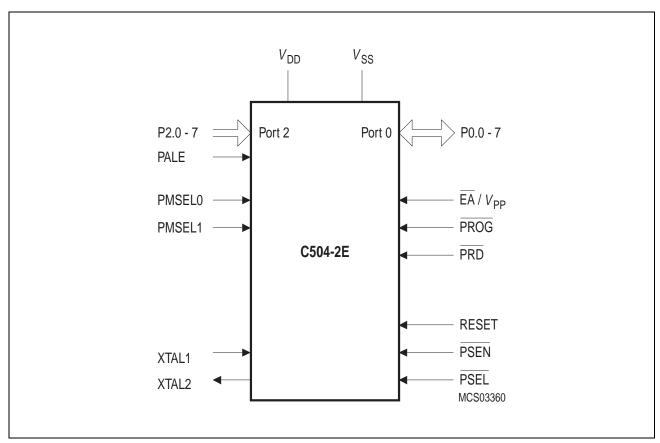


Figure 20 C504-2E Programming Mode Configuration



Pin Configuration in Programming Mode

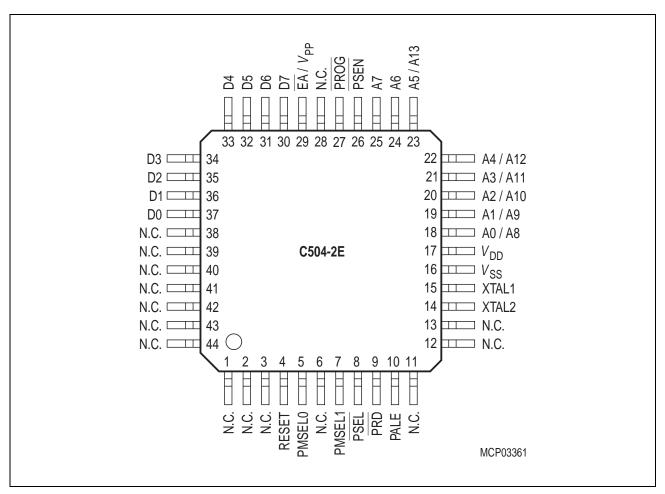


Figure 21 Pin Configuration of the C504-2E in Programming Mode (top view)



Pin Definitions

Table 11 contains the functional description of all C504-2E pins which are required for OTP memory programming.

Table 11 Pin Definitions and Functions of the C504-2E in Programming Mode

Symbol	Pin No.	I/O	Function					
	P-MQFP-44							
RESET	4	I	-	must be at s	static "1" (active) level throughout g mode.			
PMSEL0 PMSEL1	5 7	I	Programming mode selection pins These pins are used to select the different access modes in programming mode. PMSEL1,0 must satisfy setup time to the rising edge of PALE. When the logic level of PMSEL1,0 is changed, PALE must be at low level.					
			PMSEL1	PMSEL0	Access Mode			
			0	0	Reserved			
			0	1	Read version bytes			
			1	0	Program/read lock bits			
			1	1	Program/read OTP memory byte			
PSEL	8	I	This input i	s used for t	mode select he basic programming mode switched according to Figure 22.			
PRD	9	I	This input i	Programming mode read strobe This input is used for read access control for OTP memory read, version byte read, and lock bit read				
PALE	10	1	Programming address latch enable PALE is used to latch the high address lines. The high address lines must satisfy a setup and hold time to/from the falling edge of PALE. PALE must be at low level when the logic level of PMSEL1,0 is changed.					
XTAL2	14	Ο	XTAL2 Output of the inverting oscillator amplifier.					



Table 11 Pin Definitions and Functions of the C504-2E in Programming Mode (cont'd)

Symbol	Pin No.	I/O	Function
	P-MQFP-44		
XTAL1	15	I	XTAL1 Input to the oscillator amplifier.
$\overline{V_{\mathtt{SS}}}$	16	_	Ground (0 V) must be applied in programming mode.
$\overline{V_{DD}}$	17	_	Power Supply (+ 5 V) must be applied in programming mode.
P2.0 - P2.7	18 - 25	I	Address lines P2.0 - P2.7 are used as multiplexed address input lines A0 - A7 and A8 - A13. A8 - A13 must be latched with PALE.
PSEN	26	I	Program store enable This input must be at static "0" level during the whole programming mode.
PROG	27	I	Programming mode write strobe This input is used in programming mode as a write strobe for OTP memory program and lock bit write operations. During basic programming mode selection, a low level must be applied to PROG.
\overline{EA}/V_PP	29	_	Programming Voltage This pin must be held at 11.5 V ($V_{\rm PP}$) during programming of an OTP memory byte or lock bit. During an OTP memory read operation, this pin must be at $V_{\rm IH}$. This pin is also used for basic programming mode selection. For basic programming mode selection, a low level must be applied.
P0.7 - P0.0	30-37	I/O	Data lines In programming mode, data bytes are transferred via the bidirectional D7 - D0 data lines which are located at Port 0.
N.C.	1-3, 6, 11-13, 28, 38-44	_	Not Connected These pins should not be connected in programming mode.



Programming Mode Selection

The selection for the OTP programming mode can be separated into two different parts:

- Basic programming mode selection
- Access mode selection

With basic programming mode selection, the device is put into the mode in which it is possible to access the OTP memory through the programming interface logic. Further, after selection of the basic programming mode, OTP memory accesses are executed by using one of the access modes. These access modes are OTP memory byte program/read, version byte read, and program/read lock byte operations.

The basic programming mode selection scheme is shown in Figure 22.

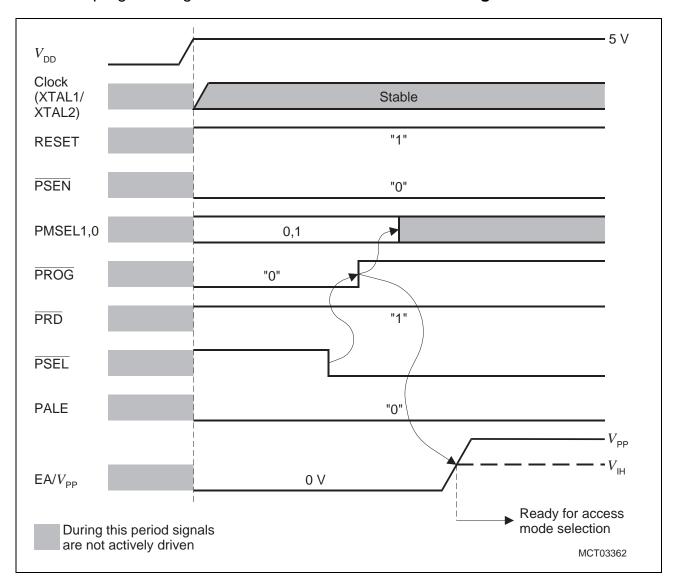


Figure 22 Basic Programming Mode Selection



Table 12 Access Modes Selection

Access Mode	EA/	PROG	PRD	PM	SEL	Address	Data
	V_{PP}			1	0	(Port 2)	(Port 0)
Program OTP memory byte	V_{PP}	Т	Н	Н	Н	A0 - A7 A8 - A15	D0 - D7
Read OTP memory byte	V_{IH}	Н	<u> </u>				
Program OTP lock bits	V_{PP}	T	Н	Н	L	_	D1,D0
Read OTP lock bits	V_{IH}	Н	77				see Table 13
Read OTP version byte	V_{IH}	Н	Т	L	Н	Byte addr. of version byte	D0 - D7

Lock Bits Programming / Read

The C504-2E has two programmable lock bits which, when programmed according to **Table 13**, provide four levels of protection for the on-chip OTP code memory.

Table 13 Lock Bit Protection Types

Lock Bits		Protection	Protection Type				
D1	D0	Level					
1	1	Level 0	The OTP lock feature is disabled. During normal operation of the C504-2E, the state of the EA pin is not latched on reset.				
1	0	Level 1	During normal operation of the C504-2E, MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory. EA is sampled and latched on reset. An OTP memory read operation is only possible according to ROM/OTP verification mode 2. Further programming of the OTP memory is disabled (reprogramming security).				
0	1	Level 2	Same as level 1, but also OTP memory read operation using ROM verification mode 2 is disabled.				
0	0	Level 3	Same as level 2; but additionally external code execution by setting \overline{EA} = low during normal operation of the C504-2E is no more possible. External code execution, which is initiated by an internal program (e.g. by an internal jump instruction above the ROM boundary), is still possible.				

Note: A '1' means that the lock bit is unprogrammed; a '0' means that lock bit is programmed.



Version Bytes

The C504-2E and C504-2R provide three version bytes at mapped address locations FC_H , FD_H , and FE_H . The information stored in the version bytes, is defined by the mask of each microcontroller step. Therefore, the version bytes can be read but not written. The three version bytes hold information as manufacturer code, device type, and stepping code.

The steppings of the C504 contain the following version byte information:

Table 14 Content of Version Bytes

Stepping	Version Byte 0, VR0 (mapped addr. FC _H)	Version Byte 1, VR1 (mapped addr. FD _H)	Version Byte 2, VR2 (mapped addr. FE _H)
C504-2R AC-Step	C5 _H	04 _H	01 _H
C504-2E ES-AA-Step	C5 _H	84 _H	01 _H
C504-2E ES-BB-Step	C5 _H	84 _H	04 _H
C504-2E CA-Step	C5 _H	84 _H	09 _H

Future steppings of the C504 will typically have a different value for version byte 2.



Absolute Maximum Ratings

Parameter	Symbol	Li	Unit	Notes	
		min.	max.		
Storage temperature	T_{ST}	- 65	150	°C	_
Voltage on $V_{\rm DD}$ pins with respect to ground ($V_{\rm SS}$)	V_{DD}	- 0.5	6.5	V	_
Voltage on any pin with respect to ground $(V_{\rm SS})$	V_{IN}	- 0.5	V _{DD} + 0.5	V	_
Input current on any pin during overload condition	_	- 10	10	mA	_
Absolute sum of all input currents during overload condition	_	-	[100 mA]	mA	_
Power dissipation	P_{DISS}	_	1	W	_

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage of the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for longer periods may affect device reliability. During absolute maximum rating overload conditions ($V_{\rm IN} > V_{\rm DD}$ or $V_{\rm IN} < V_{\rm SS}$) the voltage on $V_{\rm DD}$ pins with respect to ground ($V_{\rm SS}$) must not exceed the values defined by the absolute maximum ratings.

Operating Conditions

Parameter	Symbol	Limi	Unit	Notes	
		min.	max.		
Supply voltage	V_{DD}	4.25	5.5	V	_
Ground voltage	V_{SS}	0		V	_
Ambient temperature SAB-C504 SAF-C504 SAK-C504	$egin{array}{c} T_A \ T_A \ T_A \end{array}$	0 - 40 - 40	70 85 125	°C	_
Analog reference voltage	V_{AREF}	4	V _{DD} + 0.1	V	_
Analog ground voltage	V_{AGND}	$V_{\rm SS}$ $-$ 0.1	V _{SS} + 0.2	V	_
Analog input voltage	V_{AIN}	V_{AGND}	V_{AREF}	V	_
CPU clock	f_{CPU}	1.75	20	MHz	_



Parameter Interpretation

The parameters listed in the following partly represent the characteristics of the C504 and partly its demands on the system. To aid in interpreting the parameters right, when evaluating them for a design, they are marked in column "Symbol":

CC (Controller Characteristics):

The logic of the C504 will provide signals with the respective characteristics.

SR (**S**ystem Requirement):

The external system must provide signals with the respective characteristics to the C504.

DC Characteristics

(Operating Conditions apply)

Parameter	Symbol		Limit '	Values	Unit	Test Condition
			min.	max.		
Input low voltage (except EA, RESET, CTRAP)	V_{IL}	SR	- 0.5	0.2 V _{DD} - 0.1	V	_
Input low voltage (EA)	V_{IL1}	SR	- 0.5	0.2 V _{DD} - 0.3	V	_
Input low <u>voltage</u> (RESET, CTRAP)	V_{IL2}	SR	- 0.5	0.2 V _{DD} + 0.1	V	_
Input high voltage (except XTAL1, RESET and CTRAP)	V_{IH}	SR	0.2 V _{DD} + 0.9	$V_{\rm DD}$ + 0.5	V	11)
Input high voltage to XTAL1	V_{IH1}	SR	$0.7~V_{ m DD}$	$V_{\rm DD}$ + 0.5	V	_
Input high voltage to RESET and CTRAP	V_{IH2}	SR	$0.6~V_{ m DD}$	$V_{\rm DD}$ + 0.5	V	_
Output low voltage (Ports 1, 2, 3, COUT3)	V_{OL}	СС	_	0.45	V	$I_{\rm OL}$ = 1.6 mA ¹⁾
Output low voltage (Port 0, ALE, PSEN)	V_{OL1}	CC	_	0.45	V	$I_{\rm OL} = 3.2 \; {\rm mA}^{1)}$
Output high voltage (Ports 1, 2, 3)	V_{OH}	CC	2.4 0.9 V _{DD}	_	V	$I_{OH} = -80 \mu\text{A}$ $I_{OH} = -10 \mu\text{A}$
Output high voltage (Ports 1, 3 pins in push-pull mode and COUT3)	V_{OH1}	СС	0.9 V _{DD}	_	V	$I_{OH} = -800 \mu A$



DC Characteristics (cont'd)

(Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Condition
			min.	max.		
Output high voltage (Port 0 in external bus mode, ALE, PSEN)	V_{OH2}	СС	2.4 0.9 V _{DD}		V	$I_{OH} = -800 \mu\text{A}^{2)}$ $I_{OH} = -80 \mu\text{A}^{2)}$
Logic 0 input current (Ports 1, 2, 3)	I_{IL}	SR	– 10	- 50	μΑ	$V_{\rm IN} = 0.45 \ { m V}$
Logical 1-to-0 transition current (Ports 1, 2, 3)	I_{TL}	SR	– 65	- 650	μΑ	V _{IN} = 2 V
Input leakage current (Port 0, EA)	I_{LI}	СС	_	± 1	μΑ	$0.45 < V_{IN} < V_{DD}$
Pin capacitance	C_{IO}	CC	_	10	pF	$f_{\rm c}$ = 1 MHz, $T_{\rm A}$ = 25 °C
Overload current	I_{OV}	SR	_	± 5	mA	7) 8)
Programming voltage (C504-2E)	V_{PP}	SR	10.9	12.1	V	11.5 V ± 5% ¹⁰⁾

Power Supply Current

Parameter		Sym-	Limit Values		Unit	Test Condition	
			bol	typ.8)	max. ⁹⁾		
Active mode	C504-2R	24 MHz 40 MHz	$I_{ m DD}$ $I_{ m DD}$	27.4 43.1	35.9 57.2	mA mA	4)
	C504-2E	24 MHz 40 MHz	$I_{ m DD} \ I_{ m DD}$	20.9 31.0	27.9 41.5	mA mA	
Idle mode	C504-2R	24 MHz 40 MHz	$I_{ m DD} \ I_{ m DD}$	14.6 22.4	19.3 31.3	mA mA	5)
	C504-2E	24 MHz 40 MHz	$I_{ m DD}$ $I_{ m DD}$	12.3 16.1	16.1 20.9	mA mA	
Power-down	C504-2R		I_{PD}	1	30	μΑ	$V_{\rm DD}$ = 2 5.5 V ³⁾
mode	C504-2E		I_{PD}	35	60	μΑ	
At $\overline{\rm EA}/V_{\rm PP}$ in prog. mode	C504-2E		I_{DDP}	_	30	mA	_



Notes:

- 1) Capacitive loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the $V_{\rm OL}$ of ALE and Port 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1-to-0 transitions during bus operation. In the worst case (capacitive loading > 100 pF), the noise pulse on ALE line may exceed 0.8 V. In such cases, it may be desirable to qualify ALE with a Schmitt-trigger, or use an address latch with a Schmitt-trigger strobe input.
- 2) Capacitive loading on Ports 0 and 2 may cause the $V_{\rm OH}$ on ALE and $\overline{\rm PSEN}$ to momentarily fall below the 0.9 $V_{\rm DD}$ specification when the address lines are stabilizing.
- 3) I_{PD} (power-down mode) is measured under following conditions: EA = Port 0 = V_{DD} ; RESET = V_{SS} ; XTAL2 = N.C.; XTAL1 = V_{SS} ; V_{AGND} = V_{SS} ; all other pins are disconnected.
- 4) $I_{\rm DD}$ (active mode) is measured with: $\underline{\rm XT}$ AL1 driven with $t_{\rm CLCH}$, $t_{\rm CHCL}$ = 5 ns, $V_{\rm IL}$ = $V_{\rm SS}$ + 0.5 V, $V_{\rm IH}$ = $V_{\rm DD}$ – 0.5 V; XTAL2 = N.C.; $\overline{\rm EA}$ = Port 0 = Port 1 = RESET = $V_{\rm DD}$; all other pins are disconnected. $I_{\rm DD}$ would be slightly higher if a crystal oscillator is used (appr. 1 mA).
- 5) $I_{\rm DD}$ (idle mode) is measured with all output pins disconnected and with all peripherals disabled; XTAL1 driven with $t_{\rm CLCH}$, $t_{\rm CHCL}$ = 5 ns, $V_{\rm IL}$ = $V_{\rm SS}$ + 0.5 V, $V_{\rm IH}$ = $V_{\rm DD}$ 0.5 V; XTAL2 = N.C.; RESET = $\overline{\rm EA}$ = $V_{\rm SS}$; Port 0 = $V_{\rm DD}$; all other pins are disconnected;
- 6) Overload conditions occur if the standard operating conditions are exceeded, i.e. the voltage on any pin exceeds the specified range (i.e. $V_{\rm OV} > V_{\rm DD} + 0.5 \, {\rm V}$ or $V_{\rm OV} < V_{\rm SS} 0.5 \, {\rm V}$). The supply voltage $V_{\rm DD}$ and $V_{\rm SS}$ must remain within the specified limits. The absolute sum of input currents on all port pins may not exceed 50 mA.
- 7) Not 100 % tested, guaranteed by design characterization.
- 8) The typical $I_{\rm DD}$ values are periodically measured at $T_{\rm A}$ = + 25 °C and $V_{\rm DD}$ = 5 V but not 100% tested.
- 9) The maximum $I_{\rm DD}$ values are measured under worst case conditions ($T_{\rm A}$ = 0 °C or 40 °C and $V_{\rm DD}$ = 5.5 V)
- 10)This V_{PP} specification is valid for devices with version byte 2 = 02H or higher. Devices with version byte 2 = 01H must be programmed with V_{PP} = 12 V \pm 5%.
- 11)For the C504-2E ES-AA-step the $V_{\rm IH}$ min. for $\overline{\rm EA}$ is 0.8 $V_{\rm DD}$.



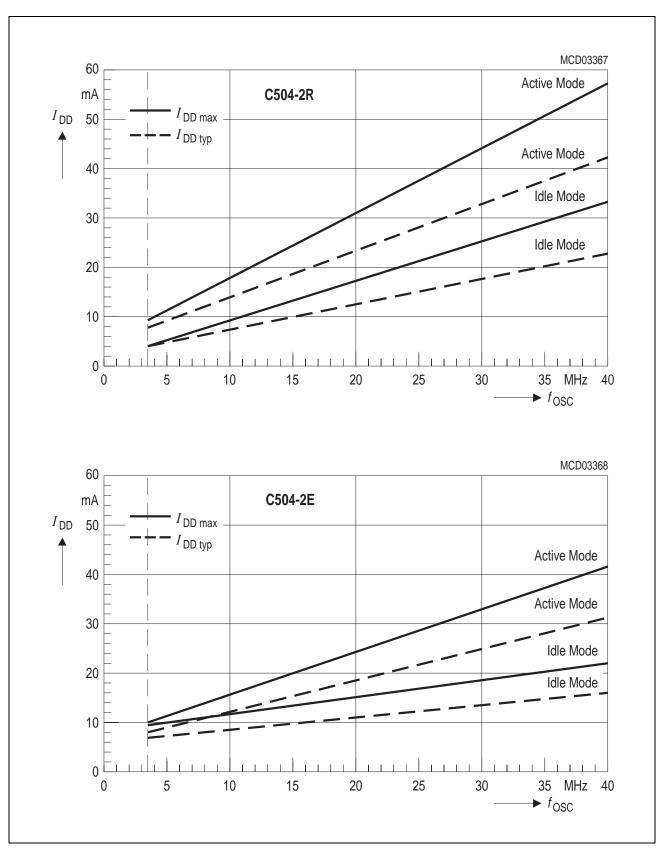


Figure 23 IDD Diagram



Power Supply Current Calculation Formulas

Parameter		Symbol	Formula
Active mode	C504-2R	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.98 \times f_{\rm OSC}$ + 3.9 1.33 $\times f_{\rm OSC}$ + 4.0
	C504-2E	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.63 \times f_{\text{OSC}} + 5.75$ $0.85 \times f_{\text{OSC}} + 7.5$
Idle mode	C504-2R	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.51 \times f_{OSC} + 2.35$ $0.75 \times f_{OSC} + 1.3$
	C504-2E	$I_{ m DD\ typ} \ I_{ m DD\ max}$	$0.24 \times f_{\text{OSC}}$ + 6.5 $0.30 \times f_{\text{OSC}}$ + 8.86

Note: $f_{\rm osc}$ is the oscillator frequency in MHz. $I_{\rm DD}$ values are given in mA.

A/D Converter Characteristics

(Operating Conditions apply)

Parameter	Syml	ool	Limit Values		Unit	Test Condition
			min.	max.		
Analog input voltage	V_{AIN}	SR	V_{AGND}	V_{AREF}	V	1)
Sample time	$t_{\mathbb{S}}$	CC	_	$64 \times t_{\text{IN}}$ $32 \times t_{\text{IN}}$ $16 \times t_{\text{IN}}$ $8 \times t_{\text{IN}}$	ns	Prescaler ÷ 32 Prescaler ÷ 16 Prescaler ÷ 8 Prescaler ÷ 4 ²⁾
Conversion cycle time	t _{ADCC}	CC	_	$384 \times t_{\text{IN}}$ $192 \times t_{\text{IN}}$ $96 \times t_{\text{IN}}$ $48 \times t_{\text{IN}}$	ns	Prescaler ÷ 32 Prescaler ÷ 16 Prescaler ÷ 8 Prescaler ÷ 4 ³⁾
Total unadjusted error	$T_{\sf UE}$	CC	_	± 2	LSB	$V_{\rm SS}$ + 0.5 V $\leq V_{\rm IN}$ $\leq V_{\rm DD}$ - 0.5 V ⁴⁾
			_	± 4	LSB	$\begin{aligned} V_{\rm SS} < V_{\rm IN} < V_{\rm SS} + 0.5 \text{ V} \\ V_{\rm DD} - 0.5 \text{ V} < V_{\rm IN} < V_{\rm DD}^{4)} \end{aligned}$
Internal resistance of reference voltage source	R_{AREF}	-SR	_	<i>t</i> _{ADC} /250 – 0.25	kΩ	t _{ADC} in [ns] ^{5) 6)}
Internal resistance of analog source	R_{ASRC}	SR	_	<i>t</i> _S /500 – 0.25	kΩ	t _S in [ns] ^{2) 6)}
ADC input capacitance	C_{AIN}	CC	_	50	pF	6)

Notes see next page.



Clock Calculation Table

Clock Prescaler Ratio	ADO	CL1, 0	t_{ADC}	$t_{\mathtt{S}}$	t_{ADCC}
÷ 32	1	1	$32 \times t_{IN}$	$64 \times t_{IN}$	$384 \times t_{IN}$
÷ 16	1	0	$16 \times t_{IN}$	$32 \times t_{IN}$	$192 \times t_{\text{IN}}$
÷ 8	0	1	$8 \times t_{IN}$	$16 \times t_{\text{IN}}$	$96 \times t_{\text{IN}}$
÷ 4	0	0	$4 \times t_{IN}$	$8 \times t_{\text{IN}}$	$48 \times t_{\text{IN}}$

Further timing conditions: $t_{ADC} \min = 500 \text{ ns}$ $t_{IN} = 2/f_{OSC} = 2 t_{CLCL}$

Notes:

- 1) $V_{\rm AIN}$ may exceed $V_{\rm AGND}$ or $V_{\rm AREF}$ up to the absolute maximum ratings. However, the conversion result in these cases will be X000_H or X3FF_H, respectively.
- 2) During the sample time, the input capacitance C_{AIN} can be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach their final voltage level within t_{S} . After the end of the sample time t_{S} , changes of the analog input voltage have no effect on the conversion result.
- 3) This parameter includes the sample time t_S, the time for determining the digital result and the time for the calibration. Values for the conversion clock t_{ADC} depend on programming and can be taken from the table on the previous page.
- 4) T_{UE} is tested at V_{AREF} = 5.0 V, V_{AGND} = 0 V, V_{DD} = 4.9 V. It is guaranteed by design characterization for all other voltages within the defined voltage range.
 If an overload condition occurs on maximum 2 not selected analog input pins and the absolute sum of input overload currents on all analog input pins does not exceed 10 mA, an additional conversion error of 1/2 LSB is permissible.
- 5) During the conversion, the ADC's capacitance must be repeatedly charged or discharged. The internal resistance of the reference source must allow the capacitance to reach their final voltage level within the indicated time. The maximum internal resistance results from the programmed conversion timing.
- 6) Not 100% tested, but guaranteed by design characterization.



AC Characteristics for C504-L / C504-2R / C504-2E

(Operating Conditions apply)

 $(C_L \text{ for Port 0, ALE and } \overline{\text{PSEN}} \text{ outputs} = 100 \text{ pF}; C_L \text{ for all other outputs} = 80 \text{ pF})$

Parameter	Symbol		Limit Values				
			12-MHz Variable Clock clock 1/t _{CLCL} = 3.5 MHz to 12 MHz				
		min.	max.	min.	max.		

Program Memory Characteristics

,							
ALE pulse width	t_{LHLL}	CC	127	_	$2t_{CLCL} - 40$	_	ns
Address setup to ALE	t_{AVLL}	CC	43	_	$t_{\text{CLCL}} - 40$	_	ns
Address hold after ALE	t_{LLAX}	CC	30	_	$t_{\text{CLCL}} - 23$	_	ns
ALE low to valid instr in	t_{LLIV}	SR	_	233	_	$4t_{\text{CLCL}} - 100$	ns
ALE to PSEN	t_{LLPL}	CC	58	_	$t_{\text{CLCL}} - 25$	_	ns
PSEN pulse width	t_{PLPH}	CC	215	_	$3t_{CLCL} - 35$	_	ns
PSEN to valid instr in	t_{PLIV}	SR	_	150	_	$3t_{CLCL} - 100$	ns
Input instruction hold after PSEN	t_{PXIX}	SR	0	_	0	_	ns
Input instruction float after PSEN	$t_{PXIZ}^{-1)}$	SR	_	63	_	<i>t</i> _{CLCL} – 20	ns
Address valid after PSEN	$t_{PXAV}^{1)}$	CC	75	_	$t_{\text{CLCL}} - 8$	_	ns
Address to valid instr in	t_{AVIV}	SR	_	302	_	5 <i>t</i> _{CLCL} – 115	ns
Address float to PSEN	t_{AZPL}	CC	0	_	0	_	ns

Notes:

¹⁾ Interfacing the C504 to devices with float times up to 75 ns is permissible. This limited bus contention will not cause any damage to Port 0 drivers.



AC Characteristics for C504-L / C504-2R / C504-2E (cont'd)

Parameter	Symbol		Limit Values				
		12-MHz clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 12 MHz			
		min.	max.	min.	max.		

External Data Memory Characteristics

•							
RD pulse width	t_{RLRH}	CC	400	_	6 <i>t</i> _{CLCL} – 100	_	ns
WR pulse width	t_{WLWH}	CC	400	_	6 <i>t</i> _{CLCL} – 100	_	ns
Address hold after ALE	t_{LLAX2}	CC	114	_	2t _{CLCL} - 53	_	ns
RD to valid data in	t_{RLDV}	SR	_	252	_	5 <i>t</i> _{CLCL} – 165	ns
Data hold after RD	t_{RHDX}	SR	0	_	0	_	ns
Data float after RD	t_{RHDZ}	SR	-	97	_	$2t_{CLCL} - 70$	ns
ALE to valid data in	t_{LLDV}	SR	_	517	_	8 <i>t</i> _{CLCL} – 150	ns
Address to valid data in	t_{AVDV}	SR	_	585	_	9t _{CLCL} – 165	ns
ALE to WR or RD	t_{LLWL}	CC	200	300	$3t_{CLCL} - 50$	$3t_{CLCL} + 50$	ns
Address valid to WR or RD	t_{AVWL}	CC	203	_	$4t_{CLCL} - 130$	_	ns
WR or RD high to ALE high	t_{WHLH}	CC	43	123	t _{CLCL} - 40	t _{CLCL} + 40	ns
Data valid to WR transition	t_{QVWX}	CC	33	_	$t_{\rm CLCL} - 50$	_	ns
Data setup before WR	t_{QVWH}	CC	433	_	$7t_{CLCL} - 150$	_	ns
Data hold after WR	t_{WHQX}	CC	33	_	$t_{\rm CLCL} - 50$	_	ns
Address float after RD	t_{RLAZ}	CC	_	0	_	0	ns

External Clock Drive Characteristics

Parameter	Symbol		Limit Values	Unit	
			Variable Clock = 3.5 MHz to 12 MHz		
		min.	max.		
Oscillator period	$t_{ m CLCL}$ SR	83.3	294	ns	
High time	t_{CHCX} SR	20	$t_{\text{CLCL}} - t_{\text{CLCX}}$	ns	
Low time	$t_{ m CLCX}$ SR	20	$t_{\text{CLCL}} - t_{\text{CHCX}}$	ns	
Rise time	t_{CLCH} SR	_	20	ns	
Fall time	t_{CHCL} SR	_	20	ns	



AC Characteristics for C504-L24 / C504-2R24 / C504-2E24

(Operating Conditions apply)

 $(C_L \text{ for Port 0, ALE and PSEN outputs} = 100 pF; <math>C_L \text{ for all other outputs} = 80 pF)$

Parameter	Symbol		Limit Values				
		24-MHz clock		Variable Clock 1/t _{CLCL} = 3.5 MHz to 24 MHz			
		min.	max.	min.	max.		

Program Memory Characteristics

ALE pulse width	t_{LHLL}	CC	43	_	$2t_{\text{CLCL}} - 40$	_	ns
Address setup to ALE	t_{AVLL}	CC	17	_	<i>t</i> _{CLCL} – 25	_	ns
Address hold after ALE	t_{LLAX}	CC	17	_	<i>t</i> _{CLCL} – 25	_	ns
ALE low to valid instr in	t_{LLIV}	SR	_	80	_	4t _{CLCL} - 87	ns
ALE to PSEN	t_{LLPL}	CC	22	_	<i>t</i> _{CLCL} – 20	_	ns
PSEN pulse width	t_{PLPH}	CC	95	_	$3t_{CLCL} - 30$	_	ns
PSEN to valid instr in	t_{PLIV}	SR	_	60	_	$3t_{\text{CLCL}} - 65$	ns
Input instruction hold after PSEN	t_{PXIX}	SR	0	_	0	_	ns
Input instruction float after PSEN	$t_{PXIZ}^{-1)}$	SR	_	32	_	<i>t</i> _{CLCL} – 10	ns
Address valid after PSEN	t_{PXAV}^{-1})CC	37	_	$t_{\text{CLCL}} - 5$	_	ns
Address to valid instr in	t_{AVIV}	SR	_	148	_	$5t_{\text{CLCL}} - 60$	ns
Address float to PSEN	t_{AZPL}	CC	0	_	0	_	ns

Notes:

1) Interfacing the C504 to devices with float times up to 37 ns is permissible. This limited bus contention will not cause any damage to Port 0 drivers.



AC Characteristics for C504-L24 / C504-2R24 / C504-2E24 (cont'd)

Parameter	Symbol	Limit Values				
			MHz ock	Variable Clock 1/t _{CLCL} = 3.5 MHz to 24 MHz		
		min.	max.	min.	max.	

External Data Memory Characteristics

					1		
RD pulse width	t_{RLRH}	CC	180	_	$6t_{CLCL} - 70$	_	ns
WR pulse width	t_{WLWH}	CC	180	_	$6t_{CLCL} - 70$	_	ns
Address hold after ALE	t_{LLAX2}	CC	56	_	2 <i>t</i> _{CLCL} – 27	_	ns
RD to valid data in	t_{RLDV}	SR	_	118	_	$5t_{CLCL} - 90$	ns
Data hold after RD	t_{RHDX}	SR	0	_	0	_	ns
Data float after RD	t_{RHDZ}	SR	_	63	_	2 <i>t</i> _{CLCL} – 20	ns
ALE to valid data in	t_{LLDV}	SR	_	200	_	8 <i>t</i> _{CLCL} – 133	ns
Address to valid data in	t_{AVDV}	SR	_	220	_	9 <i>t</i> _{CLCL} – 155	ns
ALE to WR or RD	t_{LLWL}	CC	75	175	$3t_{CLCL} - 50$	$3t_{CLCL} + 50$	ns
Address valid to WR	t_{AVWL}	CC	67	_	4 <i>t</i> _{CLCL} – 97	_	ns
WR or RD high to ALE high	t_{WHLH}	CC	17	67	<i>t</i> _{CLCL} – 25	<i>t</i> _{CLCL} + 25	ns
Data valid to WR transition	t_{QVWX}	CC	5	_	t _{CLCL} – 37	_	ns
Data setup before WR	t_{QVWH}	CC	170	_	7 <i>t</i> _{CLCL} – 122	_	ns
Data hold after WR	t_{WHQX}	CC	15	_	<i>t</i> _{CLCL} – 27	_	ns
Address float after RD	t_{RLAZ}	CC	_	0	_	0	ns

External Clock Drive

Parameter	Symb	ol		Limit Values	Unit	
			V Freq. =			
			min.	max.		
Oscillator period	t_{CLCL}	SR	41.7	294	ns	
High time	t_{CHCX}	SR	12	$t_{\text{CLCL}} - t_{\text{CLCX}}$	ns	
Low time	$t_{\sf CLCX}$	SR	12	$t_{\text{CLCL}} - t_{\text{CHCX}}$	ns	
Rise time	t_{CLCH}	SR	_	12	ns	
Fall time	t_{CHCL}	SR	_	12	ns	



AC Characteristics for C504-L40 / C504-2R40 / C504-2E40

(Operating Conditions apply)¹⁾

 $(C_L \text{ for Port 0, ALE and PSEN outputs} = 100 pF; <math>C_L \text{ for all other outputs} = 80 pF)$

Parameter	Symbol	Limit Values				
		40-MHz clock 1/		1/t _{CLCL} =	Variable Clock 1/t _{CLCL} = 3.5 MHz to 40 MHz	
		min.	max.	min.	max.	

Program Memory Characteristics

,							
ALE pulse width	t_{LHLL}	CC	35	_	2t _{CLCL} - 15	_	ns
Address setup to ALE	t_{AVLL}	CC	10	_	<i>t</i> _{CLCL} – 15	_	ns
Address hold after ALE	t_{LLAX}	CC	10	_	$t_{\rm CLCL}$ – 15	_	ns
ALE low to valid instr in	t_{LLIV}	SR	ı	55	ı	$4t_{\text{CLCL}} - 45$	ns
ALE to PSEN	t_{LLPL}	CC	10	-	$t_{\rm CLCL} - 15$	_	ns
PSEN pulse width	t_{PLPH}	CC	60	_	$3t_{CLCL} - 15$	_	ns
PSEN to valid instr in	t_{PLIV}	SR	1	25	1	$3t_{CLCL} - 50$	ns
Input instruction hold after PSEN	t_{PXIX}	SR		_	0	_	ns
Input instruction float after PSEN	$t_{PXIZ}^{(2)}$			20	_	$t_{\rm CLCL} - 5$	ns
Address valid after PSEN	$t_{PXAV}^{2)}$	CC	20	_	$t_{\text{CLCL}} - 5$	_	ns
Address to valid instr in	t_{AVIV}	SR		65		$5t_{\text{CLCL}} - 60$	ns
Address float to PSEN	t_{AZPL}	CC	- 5	_	- 5	_	ns

Notes:

- 1) SAK-C504 is not specified for 40 MHz operation.
- 2) Interfacing the C504 to devices with float times up to 25 ns is permissible. This limited bus contention will not cause any damage to Port 0 drivers.



AC Characteristics for C504-L40 / C504-2R40 / C504-2E40 (cont'd)

Parameter	Symbol	Limit Values				
		40-MHz		Variable Clock		
		clock $1/t_{CLCL} = 3.5 \text{ MHz to } 40 \text{ MHz}$				
		min. max.		min.	max.	

External Data Memory Characteristics

	1			ı	I	I	
RD pulse width	t_{RLRH}	CC	120	_	$6t_{\text{CLCL}} - 30$	_	ns
WR pulse width	t_{WLWH}	CC	120	_	$6t_{CLCL} - 30$	_	ns
Address hold after ALE	t_{LLAX2}	CC	35	_	2 <i>t</i> _{CLCL} – 15	_	ns
RD to valid data in	t_{RLDV}	SR	_	75	_	$5t_{\text{CLCL}} - 50$	ns
Data hold after RD	t_{RHDX}	SR	0		0	_	ns
Data float after RD	t_{RHDZ}	SR	_	38	_	2 <i>t</i> _{CLCL} – 12	ns
ALE to valid data in	t_{LLDV}	SR	_	150	_	$8t_{CLCL} - 50$	ns
Address to valid data in	t_{AVDV}	SR	ı	150	_	9 <i>t</i> _{CLCL} – 75	ns
ALE to WR or RD	t_{LLWL}	CC	60	90	3 <i>t</i> _{CLCL} – 15	3 <i>t</i> _{CLCL} + 15	ns
Address valid to WR	t_{AVWL}	CC	70	_	$4t_{\text{CLCL}} - 30$	_	ns
WR or RD high to ALE high	t_{WHLH}	CC	10	40	<i>t</i> _{CLCL} – 15	<i>t</i> _{CLCL} + 15	ns
Data valid to $\overline{\text{WR}}$ transition	t_{QVWX}	CC	5	_	$t_{\rm CLCL} - 20$	_	ns
Data setup before WR	t_{QVWH}	CC	125	_	$7t_{CLCL} - 50$	_	ns
Data hold after WR	t_{WHQX}	CC	5	_	<i>t</i> _{CLCL} – 20	_	ns
Address float after RD	t_{RLAZ}	CC	_	0	_	0	ns

External Clock Drive

Parameter	Symb	ol		Unit			
				Variable Clock Freq. = 3.5 MHz to 40 MHz			
			min.	max.			
Oscillator period	t_{CLCL}	SR	25	294	ns		
High time	t_{CHCX}	SR	10	$t_{\text{CLCL}} - t_{\text{CLCX}}$	ns		
Low time	t_{CLCX}	SR	10	$t_{\text{CLCL}} - t_{\text{CHCX}}$	ns		
Rise time	t_{CLCH}	SR	_	10	ns		
Fall time	t_{CHCL}	SR	_	10	ns		



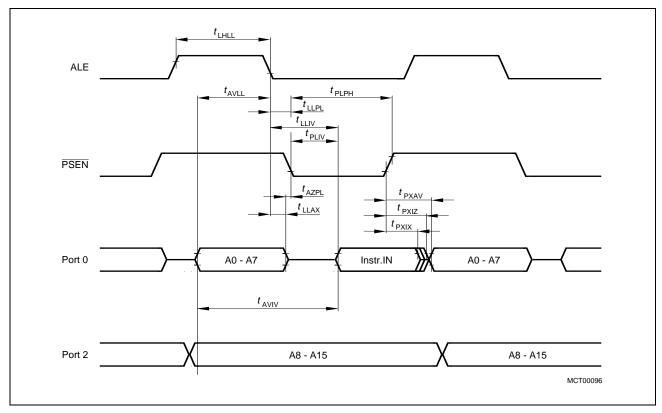


Figure 24 Program Memory Read Cycle

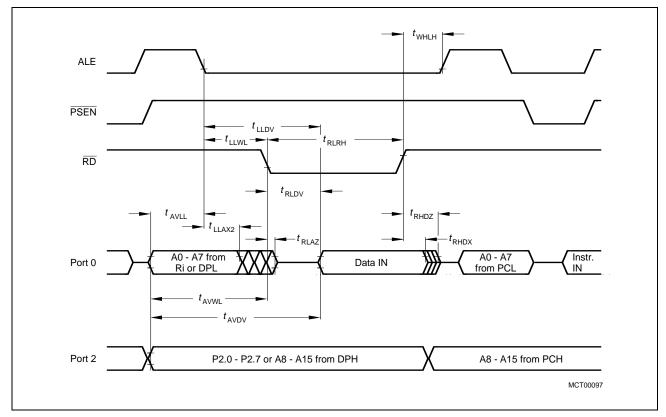


Figure 25 Data Memory Read Cycle



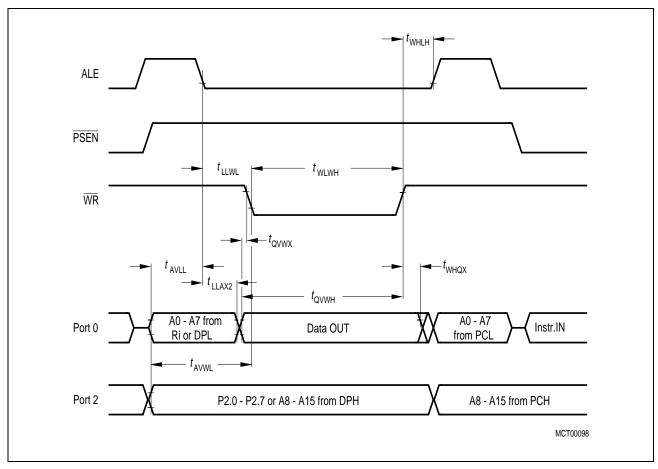


Figure 26 Data Memory Write Cycle

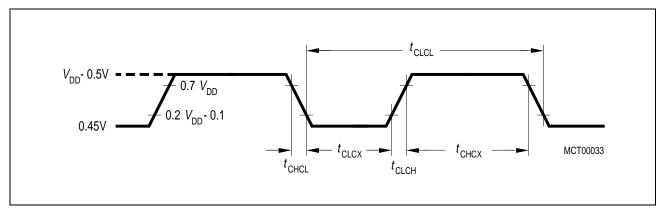


Figure 27 External Clock Cycle



AC Characteristics of Programming Mode

 $(V_{\rm DD} = 5 \text{ V} \pm 10\%; V_{\rm PP} = 11.5 \text{ V} \pm 5 \text{ \%}; T_{\rm A} = 25 \,^{\circ}\text{C} \pm 10 \,^{\circ}\text{C})$

Parameter	Symbol	Limit Val	Unit	
		min.	max.	
PALE pulse width	t_{PAW}	35	_	ns
PMSEL setup to PALE rising edge	t_{PMS}	10	_	ns
Address setup to PALE, PROG, or PRD falling edge	t_{PAS}	10	_	ns
Address hold after PALE, PROG, or PRD falling edge	t_{PAH}	10	-	ns
Address, data setup to PROG or PRD	t_{PCS}	100	_	ns
Address, data hold after PROG or PRD	t_{PCH}	0	_	ns
PMSEL setup to PROG or PRD	t_{PMS}	10	_	ns
PMSEL hold after PROG or PRD	t_{PMH}	10	_	ns
PROG pulse width	$t_{\sf PWW}$	100	_	μs
PRD pulse width	t_{PRW}	100	_	ns
Address to valid data out	t_{PAD}	_	75	ns
PRD to valid data out	t_{PRD}	_	20	ns
Data hold after PRD	t_{PDH}	0	_	ns
Data float after PRD	t_{PDF}	_	20	ns
PROG low pulses	t _{PWH1}	1	-	μs
PRD high between two consecutive PRD low pulses	t _{PWH2}	100	-	ns
XTAL clock period	t_{CLKP}	83.3	285.7	ns

Note:

 $V_{\rm PP}$ = 11.5 V ± 5% is valid for devices with version byte 2 = 02_H or higher. Devices with version byte 2 = 01_H must be programmed with $V_{\rm PP}$ = 12 V ± 5%.



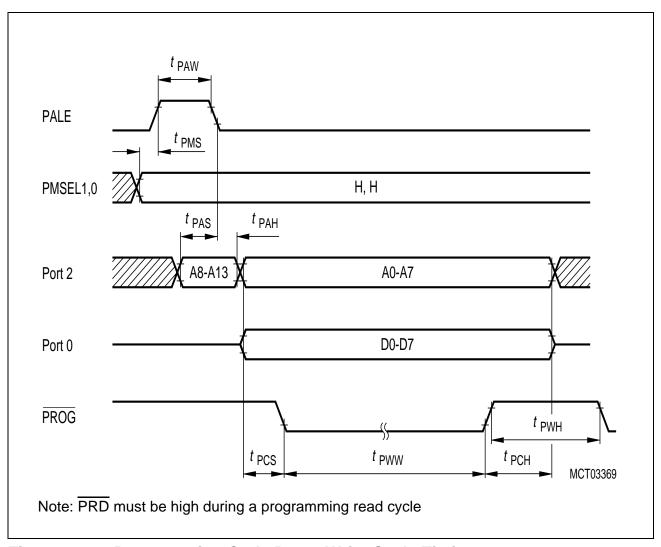


Figure 28 Programming Code Byte - Write Cycle Timing



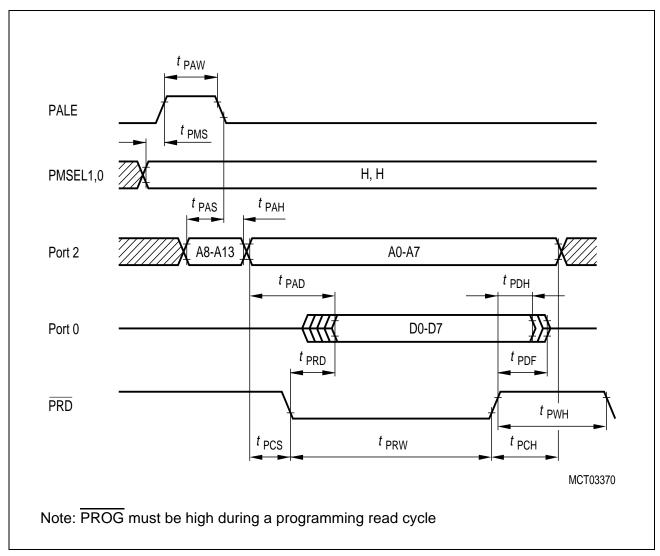


Figure 29 Verify Code Byte - Read Cycle Timing



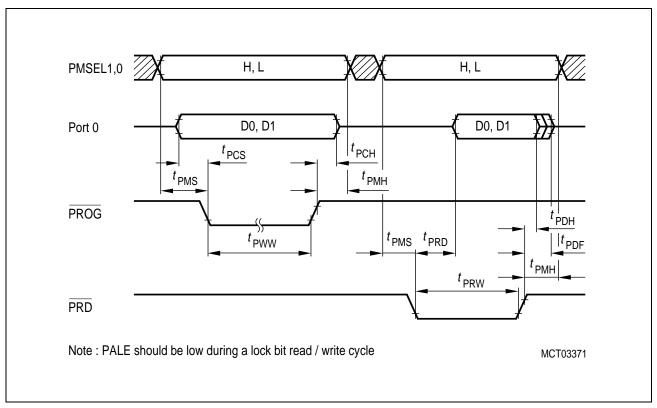


Figure 30 Lock Bit Access Timing

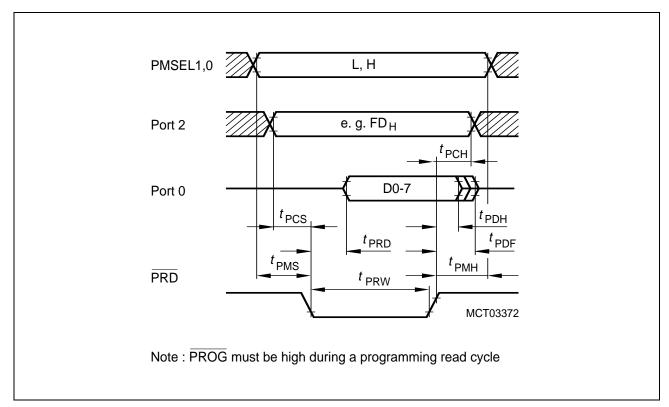


Figure 31 Version Byte Read Timing



ROM/OTP Verification Characteristics for C504-2R / C504-2E ROM Verification Mode 1 (C504-2R only)

Parameter	Symbol	Limit \	Unit	
		min.	max.	
Address to valid data	t_{AVQV}	_	10 t _{CLCL}	ns

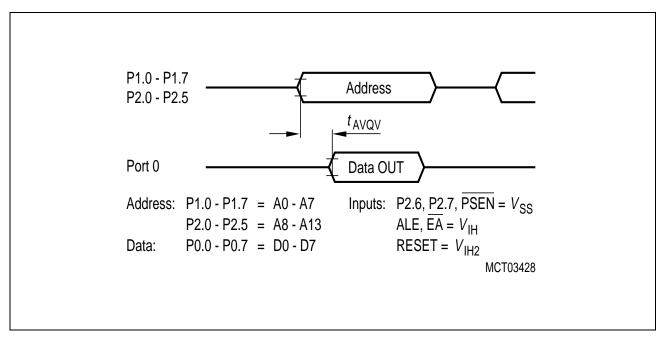


Figure 32 ROM Verification Mode 1



ROM/OTP Verification Mode 2

Parameter	Symbol		Unit		
		min.	typ	max.	
ALE pulse width	t_{AWD}	_	2 t _{CLCL}	_	ns
ALE period	t_{ACY}	_	12 t _{CLCL}	_	ns
Data valid after ALE	t_{DVA}	_	_	4 t _{CLCL}	ns
Data stable after ALE	t_{DSA}	8 t _{CLCL}	_	_	ns
P3.5 setup to ALE low	t_{AS}	_	t_{CLCL}	_	ns
Oscillator frequency	1/t _{CLCL}	4	_	6	MHz

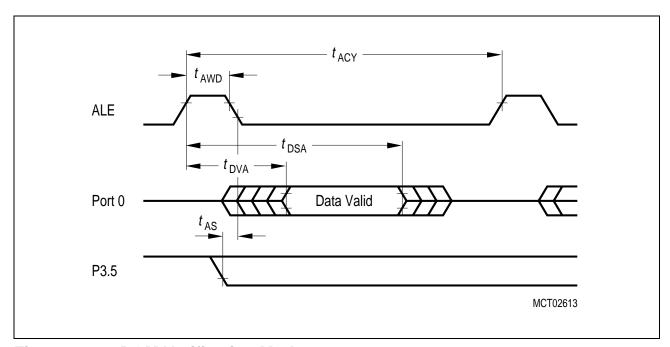
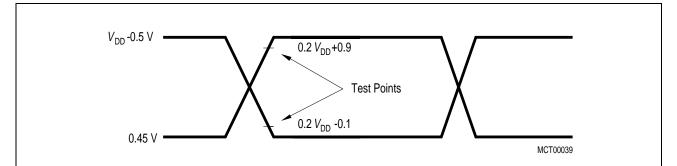


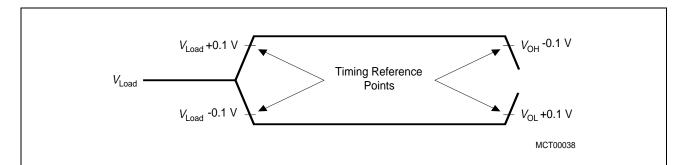
Figure 33 ROM Verification Mode 2





AC Inputs during testing are driven at $V_{\rm DD}$ – 0.5 V for a logic '1' and 0.45 V for a logic '0'. Timing measurements are made at $V_{\rm IHmin}$ for a logic '1' and $V_{\rm ILmax}$ for a logic '0'.

Figure 34 AC Testing: Input, Output Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded $V_{\rm OH}/V_{\rm OL}$ level occurs. $I_{\rm OI}/I_{\rm OH} \ge \pm 20$ mA

Figure 35 AC Testing: Float Waveforms

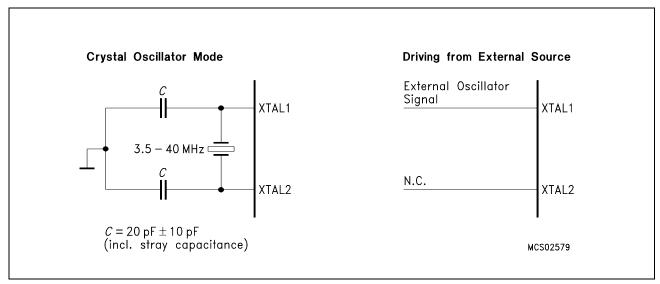
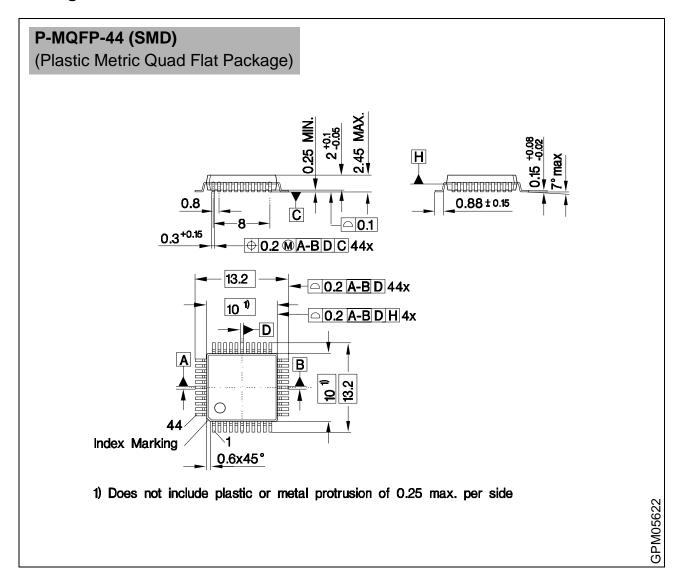


Figure 36 Recommended Oscillator Circuits for Crystal Oscillator



Package Information



Sorts of Packing

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

SMD = Surface Mounted Device

Dimensions in mm

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